T13 Data Sheet

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Contents

Introduction

The T13 FPGA features the high-density, low-power Efinix® Quantum™ architecture wrapped with an I/O interface for easy integration. With a high I/O to logic ratio and differential I/O support, T13 FPGAs supports a variety of applications that need wide I/O connectivity. The T13 also includes a MIPI D-PHY with a built-in, royalty-free CSI-2 controller, which is the most popular camera interface used in the mobile industry. The carefully tailored combination of core resources and I/O provides enhanced capability for applications such as embedded vision, voice and gesture recognition, intelligent sensor hubs, power management, and LED drivers.

Features

- High-density, low-power Quantum™ architecture
- Built on SMIC 40 nm process
- Core leakage current as low as 6.8 mA[1]
- FPGA interface blocks
  - GPIO
  - PLL
  - LVDS 800 Mbps per lane with up to 13 TX pairs and 13 RX pairs
  - MIPI DPHY with CSI-2 controller hard IP, 1.5 Gbps per lane
- Programmable high-performance I/O
  - Supports 1.8, 2.5, and 3.3 V single-ended I/O standards and interfaces
- Flexible on-chip clocking
  - 16 low-skew global clock signals can be driven from off-chip external clock signals or PLL synthesized clock signals
  - PLL support
- Flexible device configuration
  - Standard SPI interface (active, passive, and daisy chain)
  - JTAG interface
  - Optional Mask Programmable Memory (MPM) capability
- Fully supported by the Efinity® software, an RTL-to-bitstream compiler

Table 1: T13 FPGA Resources

LEs[2]	Global Clock Networks	Global Control Networks	Embedded Memory (kbits)	Embedded Memory Blocks (5 Kbits)	Embedded Multipliers
12,828	Up to 16	Up to 16	727.04	142	24

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[1] Typical leakage current for BGA256 package only.
[2] Logic capacity in equivalent LE counts.

Table 2: T13 Package-Dependent Resources

Resource	BGA169	BGA256
Available GPIO[3]	73	195
Global clocks from GPIO pins	4	16
Global controls from GPIO pins	3	16
PLLs	5	5
LVDS	8 TX pairs 12 RX pairs	13 TX pairs 13 RX pairs
MIPI DPHY with CSI-2 controller (4 data lanes, 1 clock lane)	2 TX instances 2 RX instances	–

Available Package Options

Table 3: Available Packages

Package	Dimensions (mm x mm)	Pitch (mm)
169-ball FBGA	9 x 9	0.65
256-ball FBGA	13 x 13	0.8

Device Core Functional Description

T13 FPGAs feature an eXchangeable Logic and Routing (XLR) cell that Efinix has optimized for a variety of applications. Trion® FPGAs contain three building blocks constructed from XLR cells: logic elements, embedded memory blocks, and multipliers. Each FPGA in the Trion® family has a custom number of building blocks to fit specific application needs. As shown in the following figure, the FPGA includes I/O ports on all four sides, as well as columns of XLR cells, memory, and multipliers. A control block within the FPGA handles configuration.

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[3] The LVDS I/O pins are dual-purpose. The full number of GPIO are available when all LVDS I/O pins are in GPIO mode. GPIO and LVDS as GPIO supports different features. See **Table 5: Features for GPIO and LVDS as GPIO** on page 10.

Figure 1: T13 FPGA Block Diagram

Quantum Fabric

I/O Ports from Core to Device Interface

XLR Cells and Routing

Each Device Contains Unique
Interface Blocks such as GPIO
and PLL

Note: The number and locations of rows and
columns are shown for illustration purposes
only. The actual number and position depends
on the core.
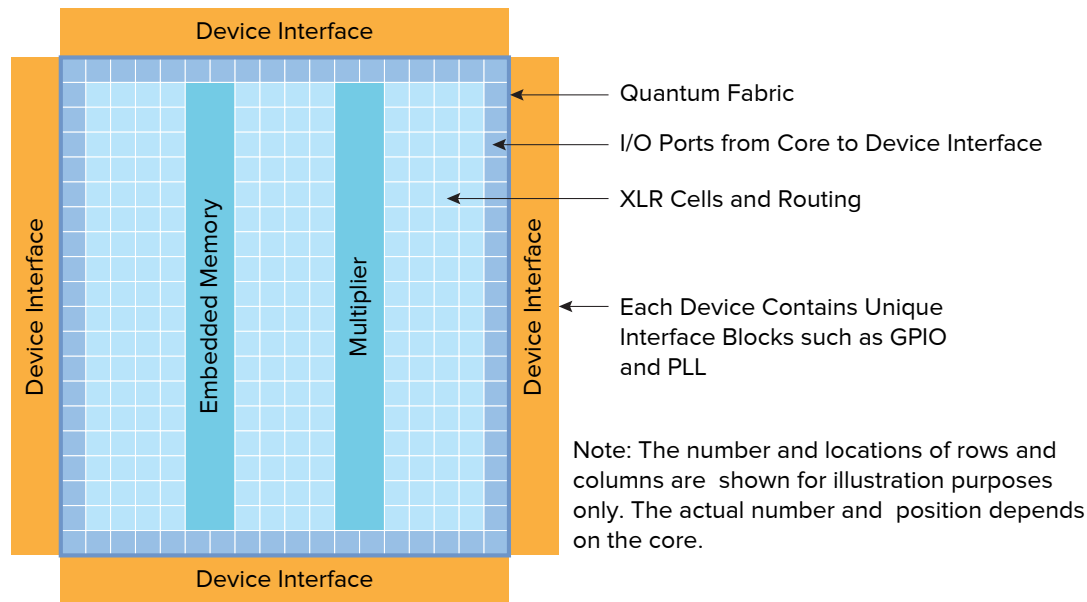
XLR Cell

The eXchangeable Logic and Routing (XLR) cell is the basic building block of the Quantum™
architecture. The Efinix XLR cell combines logic and routing and supports both functions
interchangeably. This unique innovation greatly enhances the transistor flexibility and
utilization rate, thereby reducing transistor counts and silicon area significantly.

Logic Cell

The logic cell comprises a 4-input LUT or a full adder plus a register (flipflop). You can
program each LUT as any combinational logic function with four inputs. You can configure
multiple logic cells to implement arithmetic functions such as adders, subtractors, and
counters.

Figure 2: Logic Cell Block Diagram
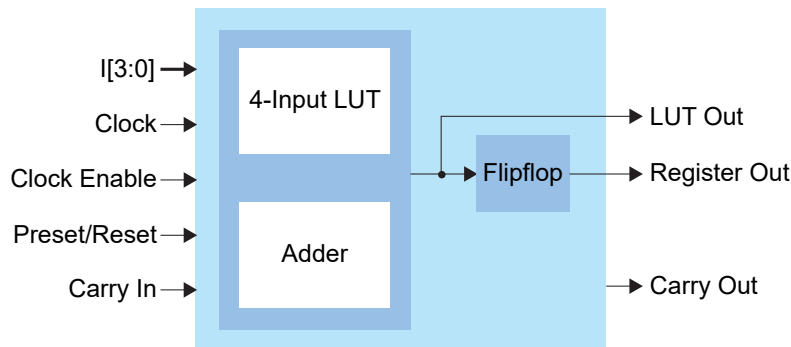
Embedded Memory

The core has 5-kbit high-speed, synchronous, embedded SRAM memory blocks. Memory blocks can operate as single-port RAM, simple dual-port RAM, true dual-port RAM, FIFOs, or ROM. You can initialize the memory content during configuration. The Efinity® software includes a memory cascading feature to connect multiple blocks automatically to form a larger array. This feature enables you to instantiate deeper or wider memory modules.

The memory read and write ports have the following modes for addressing the memory (depth x width):

256 x 16	1024 x 4	4096 x 1	512 x 10
512 x 8	2048 x 2	256 x 20	1024 x 5

The read and write ports support independently configured data widths.

Figure 3: Embedded Memory Block Diagram (True Dual-Port Mode)
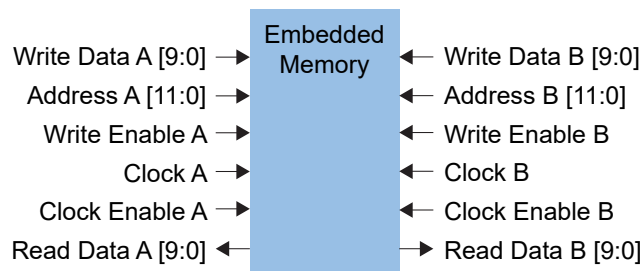
Multipliers

The FPGA has high-performance multipliers that support 18 x 18 fixed-point multiplication. Each multiplier takes two signed 18-bit input operands and generates a signed 36-bit output product. The multiplier has optional registers on the input and output ports.

Figure 4: Multiplier Block Diagram

Global Clock Network

The Quantum™ core fabric supports up to 16 global clock (GCLK) signals feeding 16 pre-built global clock networks. Global clock pins (GPIO), PLL outputs, and core-generated clocks can drive the global clock network

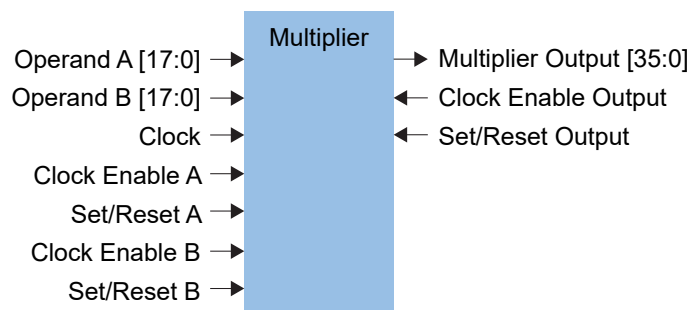The Quantum™ compute fabric supports up to 16 global clock (GCLK) signals feeding 16 pre-built global clock networks. Global clock pins (GPIO), PLL outputs, oscillator output, and core-generated clocks can drive the global clock network.

The global clock networks are balanced clock trees that feed all FPGA modules. Each network has dedicated clock-enable logic to save power by disabling the clock tree at the root. The logic dynamically enables/disables the network and guarantees no glitches at the output.

Figure 5: Global Clock Network
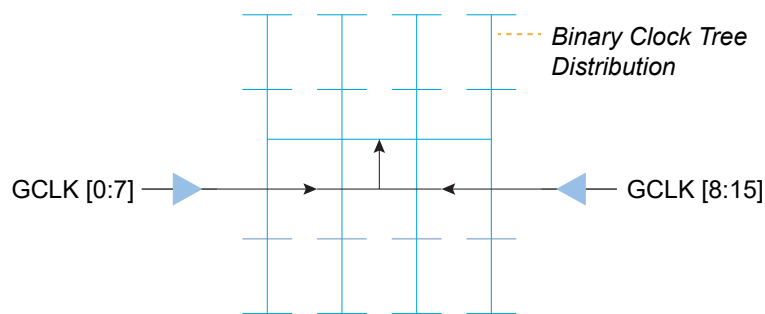
Device Interface Functional Description

The device interface wraps the core and routes signals between the core and the device I/O pads through a signal interface. Because they use the flexible Quantum™ architecture, devices in the Trion® family support a variety of interfaces to meet the needs of different applications.

Learn more: The following sections describe the available device interface features in T13 FPGAs. Refer to the Trion® Interfaces User Guide for details on the Efinity® Interface Designer settings.

Interface Block Connectivity

The FPGA core fabric connects to the interface blocks through a signal interface. The interface blocks then connect to the package pins. The core connects to the interface blocks using three types of signals:

- *Input*—Input data or clock to the FPGA core
- *Output*—Output from the FPGA core
- *Clock output*—Clock signal from the core clock tree

Figure 6: Interface Block and Core Connectivity
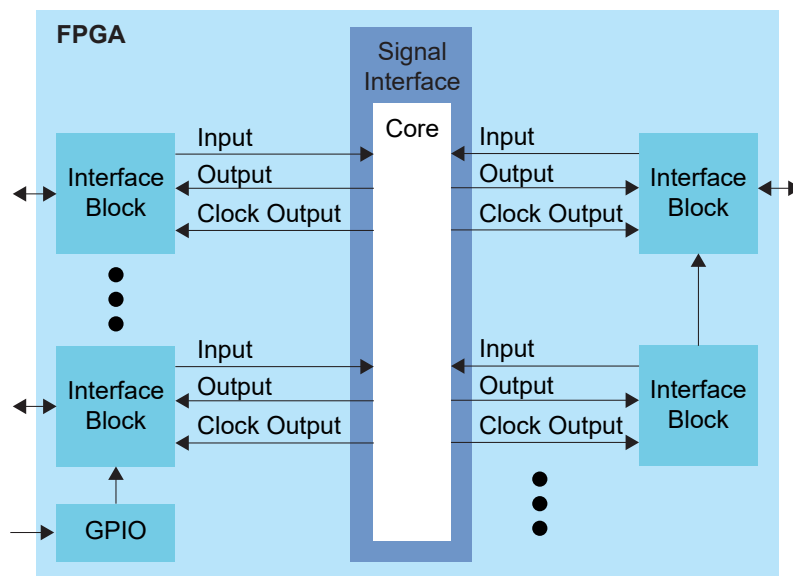
GPIO blocks are a special case because they can operate in several modes. For example, in alternate mode the GPIO signal can bypass the signal interface and directly feed another interface block. So a GPIO configured as an alternate input can be used as a PLL reference clock without going through the signal interface to the core.

When designing for Trion® FPGAs, you create an RTL design for the core and also configure the interface blocks. From the perspective of the core, outputs from the core are inputs to the interface block and inputs to the core are outputs from the interface block.

The Efinity netlist always shows signals from the perspective of the core, so some signals do not appear in the netlist:

- GPIO used as reference clocks are not present in the RTL design, they are only visible in the interface block configuration of the Efinity® Interface Designer.
- The FPGA clock tree is connected to the interface blocks directly. Therefore, clock outputs from the core to the interface are not present in the RTL design, they are only part of the interface configuration (this includes GPIO configured as output clocks).

The following sections describe the different types of interface blocks in the T13. Signals and block diagrams are shown from the perspective of the interface, not the core.

General-Purpose I/O Logic and Buffer

The GPIO support the 3.3 V LVTTL and 1.8 V, 2.5 V, and 3.3 V LVCMOS I/O standards. The GPIOs are grouped into banks. Each bank has its own VCCIO that sets the bank voltage for the I/O standard.

Each GPIO consists of I/O logic and an I/O buffer. I/O logic connects the core logic to the I/O buffers. I/O buffers are located at the periphery of the device.

The I/O logic comprises three register types:

- *Input*—Capture interface signals from the I/O before being transferred to the core logic
- *Output*—Register signals from the core logic before being transferred to the I/O buffers
- *Output enable*—Enable and disable the I/O buffers when I/O used as output

Table 4: GPIO Modes

GPIO Mode	Description
Input	Only the input path is enabled; optionally registered. If registered, the input path uses the input clock to control the registers (positively or negatively triggered). Select the alternate input path to drive the alternate function of the GPIO. The alternate path cannot be registered. In DDIO mode, two registers sample the data on the positive and negative edges of the input clock, creating two data streams.
Output	Only the output path is enabled; optionally registered. If registered, the output path uses the output clock to control the registers (positively or negatively triggered). The output register can be inverted. In DDIO mode, two registers capture the data on the positive and negative edges of the output clock, multiplexing them into one data stream.
Bidirectional	The input, output, and OE paths are enabled; optionally registered. If registered, the input clock controls the input register, the output clock controls the output and OE registers. All registers can be positively or negatively triggered. Additionally, the input and output paths can be registered independently. The output register can be inverted.
Clock output	Clock output path is enabled.

Table 5: Features for GPIO and LVDS as GPIO

LVDS as GPIO are LVDS pins that act as GPIOs instead of the LVDS function.

Package	Supported Features	
	GPIO	LVDS as GPIO
BGA169 BGA256	DDIO Schmitt Trigger Variable Drive Strength Pull-up Pull-down Slew Rate	Pull-up

Important: Efinix® recommends that you limit the number of LVDS as GPIO set as output and bidirectional to 16 per bank to avoid switching noise. The Efinity software issues a warning if you exceed the recommended limit.

During configuration, all GPIO pins excluding LVDS as GPIO are configured in weak pull-up mode.

During user mode, unused GPIO pins are tri-stated and configured in weak pull-up mode. You can change the default mode to weak pull-down in the Interface Designer.

Note: Refer to Table 42: Single-Ended I/O Buffer Drive Strength Characteristics on page 39 for more information.

Complex I/O Buffer

Figure 7: I/O Interface Block
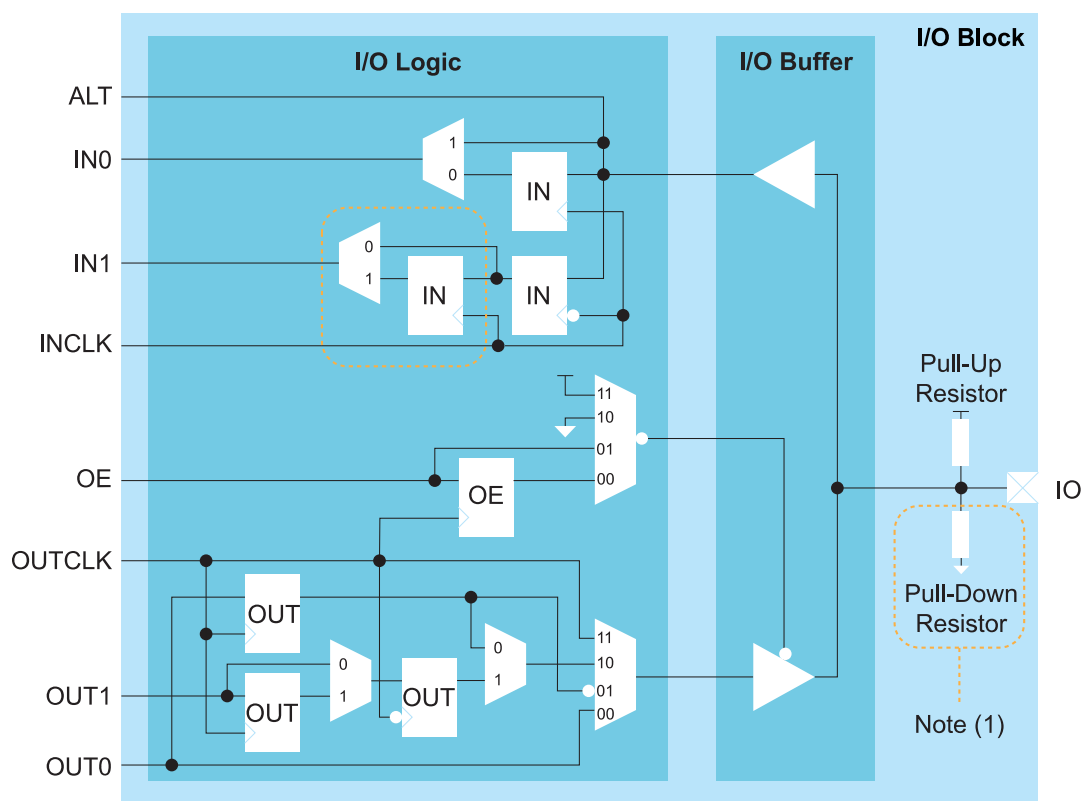
1. GPIO pins using LVDS resources do not have a pull-down resistor.

> ℹ️ **Note:** LVDS as GPIO do not have double data I/O (DDIO).

Table 6: GPIO Signals (Interface to FPGA Fabric)

Signal	Direction	Description
IN[1:0]	Output	Input data from the GPIO pad to the core fabric.
		IN0 is the normal input to the core. In DDIO mode, IN0 is the data captured on the positive clock edge (HI pin name in the Interface Designer) and IN1 is the data captured on the negative clock edge (LO pin name in the Interface Designer).
ALT	Output	Alternative input connection (in the Interface Designer, **Register Option** is **none**).
		Alternative connections are GCLK, GCTRL, PLL_CLKIN, MIPI_CLKIN.[4]
OUT[1:0]	Input	Output data to GPIO pad from the core fabric.
		OUT0 is the normal output from the core. In DDIO mode, OUT0 is the data captured on the positive clock edge (HI pin name in the Interface Designer) and OUT1 is the data captured on the negative clock edge (LO pin name in the Interface Designer).
OE	Input	Output enable from core fabric to the I/O block. Can be registered.
OUTCLK	Input	Core clock that controls the output and OE registers. This clock is not visible in the user netlist.
INCLK	Input	Core clock that controls the input registers. This clock is not visible in the user netlist.

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[4] MIPI_CLKIN is only available in packages that support MIPI.

Table 7: GPIO Pads

Signal	Direction	Description
IO	Bidirectional	GPIO pad.

Double-Data I/O

T13 FPGAs support double data I/O (DDIO) on certain input and output registers. In this mode, the DDIO register captures data on both positive and negative clock edges. The core receives 2 bit wide data from the interface.

In normal mode, the interface receives or sends data directly to or from the core on the positive and negative clock edges. In resync mode, the interface resynchronizes the data to pass both signals on the positive clock edge only.

Not all GPIO support DDIO; additionally, LVDS as GPIO (that is, single ended I/O) do not support DDIO functionality.

Note: The Resource Assigner in the Efinity® Interface Designer shows which GPIO support DDIO.

Figure 8: DDIO Input Timing Waveform
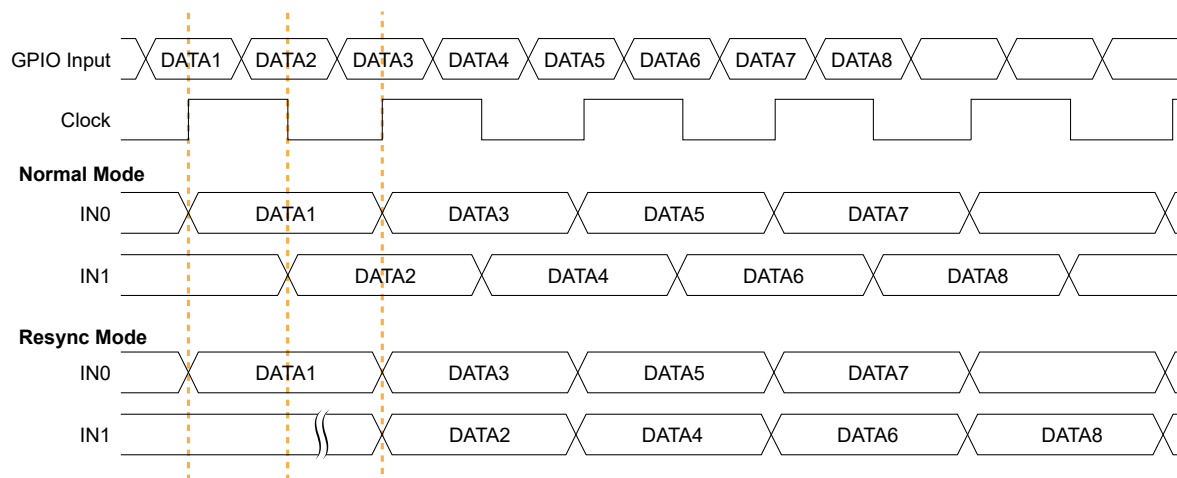
In resync mode, the IN1 data captured on the falling clock edge is delayed one half clock cycle.

In the Interface Designer, IN0 is the HI pin name and IN1 is the LO pin name.

Figure 9: DDIO Output Timing Waveform

Normal Mode

Clock				
OUT0	DATA1	DATA3	DATA5	DATA7
OUT1	DATA2	DATA4	DATA6	DATA8
GPIO Output	DATA1 DATA2 DATA3 DATA4 DATA5 DATA6 DATA7 DATA8			

Resync Mode

Clock				
OUT0	DATA1	DATA3	DATA5	DATA7
OUT1	DATA2	DATA4	DATA6	DATA8
GPIO Output	DATA1 DATA2 DATA3 DATA4 DATA5 DATA6 DATA7 DATA8			
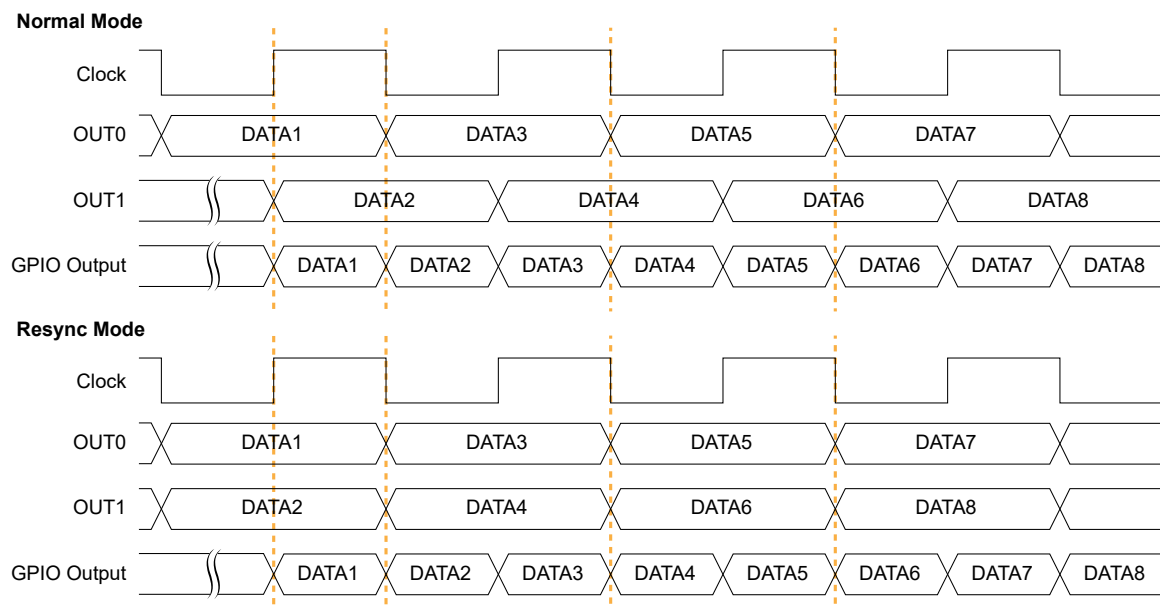
In the Interface Designer, OUT0 is the HI pin name and OUT1 is the LO pin name.

Clock and Control Distribution Network

The global clock network is distributed through the device to provide clocking for the core's LEs, memory, multipliers, and I/O blocks. Designers can access the T13 global clock network using the global clock GPIO pins, PLL outputs, and core-generated clocks. Similarly, the T13 has GPIO pins (the number varies by package) that the designer can configure as control inputs to access the high-fanout network connected to the LE's set, reset, and clock enable signals.

Learn more: Refer to the T13 Pinout for information on the location and names of these pins.

I/O Banks

Efinix FPGAs have input/output (I/O) banks for general-purpose usage. Each I/O bank has independent power pins. The number and voltages supported vary by FPGA and package.

Some I/O banks are merged at the package level by sharing VCCIO pins. Merged banks have underscores (_) between banks in the name (e.g., 1B_1C means 1B and 1C are connected).

Table 8: I/O Banks by Package

Package	I/O Banks	Voltage (V)	Banks with DDIO Support	Merged Banks
BGA169	1A - 1E, 3A - 3E	1.8, 2.5, 3.3	1B, 1C, 1D, 3B, 3C, 3D, 3E	1B_1C_1D, 3A_3B, 3C_3D_3E
	4A, 4B	3.3	–	–
BGA256	1A - 1E, 3A - 3E	1.8, 2.5, 3.3	1B, 1C, 1D, 3B, 3C, 3D, 3E	1B_1C, 1D_1E. 3A_3B_3C, 3D_3E
	4A, 4B	3.3	–	–

Learn more: Refer to the T13 Pinout for information on the I/O bank assignments.

PLL

The T13 has 5 available PLLs to synthesize clock frequencies.

You can use the PLL to compensate for clock skew/delay via external or internal feedback to meet timing requirements in advanced application. The PLL reference clock has up to four sources. You can dynamically select the PLL reference clock with the CLKSEL port. (Hold the PLL in reset when dynamically selecting the reference clock source.)

One of the PLLs can use an LVDS RX buffer to input it's reference clock.

The PLL consists of a pre-divider counter (N counter), a feedback multiplier counter (M counter), a post-divider counter (O counter), and output divider.

Note: Refer to T13 Interface Floorplan on page 51 for the location of the PLLs on the die. Refer to Table 65: General Pinouts on page 47 for the PLL reference clock resource assignment.

Figure 10: PLL Block Diagram
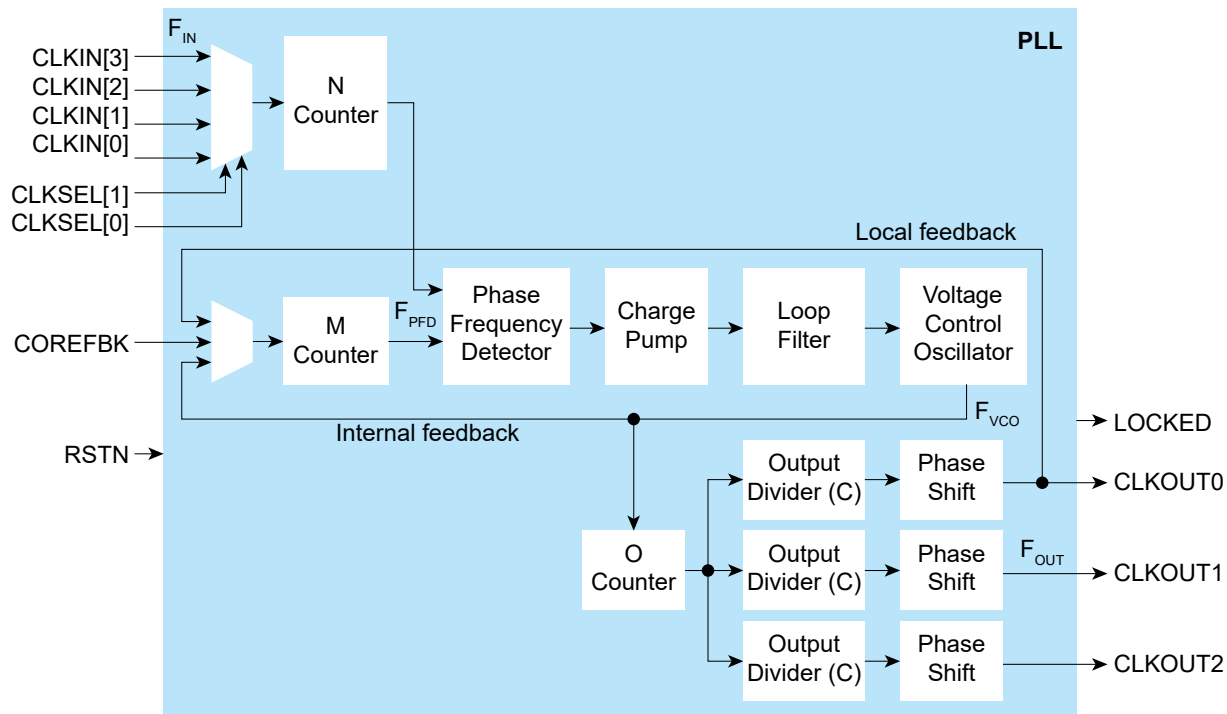
The counter settings define the PLL output frequency:

Internal Feedback Mode	Local and Core Feedback Mode	Where:
$F_{PFD} = F_{IN} / N$ $F_{VCO} = F_{PFD} \times M$ $F_{OUT} = (F_{IN} \times M) / (N \times O \times C)$	$F_{PFD} = F_{IN} / N$ $F_{VCO} = (F_{PFD} \times M \times O \times C_{FBK})$ [5] $F_{OUT} = (F_{IN} \times M \times C_{FBK}) / (N \times C)$	F_{VCO} is the voltage control oscillator frequency F_{OUT} is the output clock frequency F_{IN} is the reference clock frequency F_{PFD} is the phase frequency detector input frequency C is the output divider

ⓘ **Note:** F_{IN} must be within the values stated in **PLL Timing and AC Characteristics** on page 46.

Figure 11: PLL Interface Block Diagram

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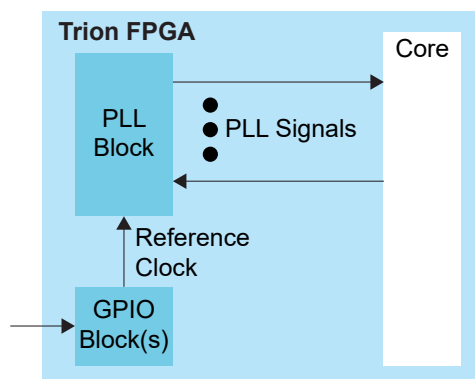
[5] (M x O x C_{FBK}) must be ≤ 255.

Table 9: PLL Signals (Interface to FPGA Fabric)

Signal	Direction	Description
CLKIN[3:0]	Input	Reference clocks driven by I/O pads or core clock tree.
CLKSEL[1:0]	Input	You can dynamically select the reference clock from one of the clock in pins.
RSTN	Input	Active-low PLL reset signal. When asserted, this signal resets the PLL; when de-asserted, it enables the PLL. Connect this signal in your design to power up or reset the PLL. Assert the RSTN pin for a minimum pulse of 10 ns to reset the PLL. Assert RSTN when dynamically changing the selected PLL reference clock.
COREFBK	Input	Connect to a clock out interface pin when the the PLL feedback mode is set to core.
CLKOUT0 CLKOUT1 CLKOUT2	Output	PLL output. The designer can route these signals as input clocks to the core's GCLK network.
LOCKED	Output	Goes high when PLL achieves lock; goes low when a loss of lock is detected. Connect this signal in your design to monitor the lock status.

Table 10: PLL Interface Designer Settings - Properties Tab

Parameter	Choices	Notes
Instance Name	User defined	
PLL Resource		The resource listing depends on the FPGA you choose.
Clock Source	External	PLL reference clock comes from an external pin.
	Dynamic	PLL reference clock comes from an external pin or the core, and is controlled by the clock select bus.
	Core	PLL reference clock comes from the core.
Automated Clock Calculation		Pressing this button launches the PLL Clock Caclulation window. The calculator helps you define PLL settings in an easy-to-use graphical interface.

Table 11: PLL Interface Designer Settings - Manual Configuration Tab

Parameter	Choices	Notes
Reset Pin Name	User defined	
Locked Pin Name	User defined	
Feedback Mode	Internal	PLL feedback is internal to the PLL resulting in no known phase relationship between clock in and clock out.
	Local	PLL feedback is local to the PLL. Aligns the clock out phase with clock in.
	Core	PLL feedback is from the core. The feedback clock is defined by the COREFBK connection, and must be one of the three PLL output clocks. Aligns the clock out phase with clock in and removes the core clock delay.
Reference clock Frequency (MHz)	User defined	
Multiplier (M)	1 - 255 (integer)	M counter.
Pre Divider (N)	1 - 15 (integer)	N counter.
Post Divider (O)	1, 2, 4, 8	O counter.
Clock 0, Clock 1, Clock 2	On, off	Use these checkboxes to enable or disable clock 0, 1, and 2.
Pin Name	User defined	Specify the pin name for clock 0, 1, or 2.
Divider (C)	1 to 256	Output divider.
Phase Shift (Degree)	0, 45, 90, 135, 180, or 270	Phase shift CLKOUT by 0, 45, 90, 135, 180, or 270 degrees. 180, and 270 require the C divider to be 2. 45 and 135 require the C divider to be 4. 90 requires the C divider to be 2 or 4. To phase shift 225 degrees, select 45 and invert the clock at the destination. To phase shift 315 degrees, select 135 and invert the clock at the destination.
Use as Feedback	On, off	

Table 12: PLL Reference Clock Resource Assignments (BGA169 and BGA256)

PLL	REFCLK1	REFCLK2
PLL_BR0[6]	Differential: GPIOB_CLKP0, GPIOB_CLKN0 Single Ended: GPIOB_CLKP0	GPIOR_157_PLLIN
PLL_TR0	GPIOR_76_PLLIN0	GPIOR_77_PLLIN1
PLL_TR1	GPIOR_76_PLLIN0	GPIOR_77_PLLIN1
PLL_TL0	GPIOL_74_PLLIN0	GPIOL_75_PLLIN1
PLL_TL1	GPIOL_74_PLLIN0	GPIOL_75_PLLIN1

[6] PLL_BR0 can be used as the PHY clock for DDR DRAM block.

LVDS

The LVDS hard IP transmitters and receivers operate independently.

- LVDS TX consists of LVDS transmitter and serializer logic.
- LVDS RX consists of LVDS receiver, on-die termination, and de-serializer logic.

The T13 has one PLL for use with the LVDS receiver.

ⓘ **Note:** You can use the LVDS TX and LVDS RX channels as 3.3 V single-ended GPIO pins, which support a weak pull-up but do not support a Schmitt trigger or variable drive strength. When using LVDS as GPIO, make sure to leave at least 2 pairs of unassigned LVDS pins between any GPIO and LVDS pins in the same bank. This separation reduces noise. The Efinity software issues an error if you do not leave this separation.

The LVDS hard IP has these features:

- Dedicated LVDS TX and RX channels (the number of channels is package dependent), and one dedicated LVDS RX clock
- Up to 800 Mbps for LVDS data transmit or receive
- Supports serialization and deserialization factors: 8:1, 7:1, 6:1, 5:1, 4:1, 3:1, and 2:1
- Ability to disable serialization and deserialization
- Source synchronous clock output edge-aligned with data for LVDS transmitter and receiver
- 100 Ω on-die termination resistor for the LVDS receiver

ⓘ **Note:** The LVDS RX supports the sub-lvds, slvs, HiVcm, RSDS and 3.3 V LVPECL differential I/O standards with a transfer rate of up to 800 Mbps.

LVDS TX

Figure 12: LVDS TX Interface Block Diagram
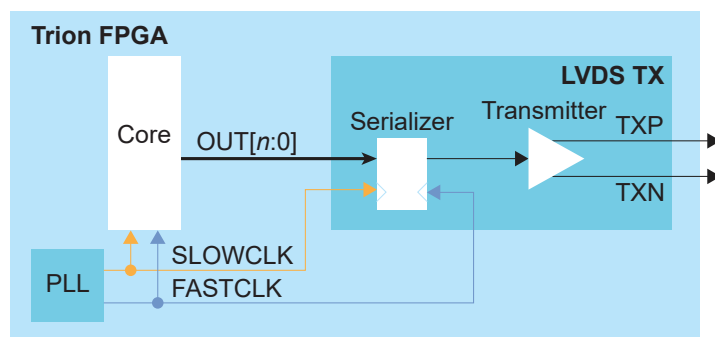
Table 13: LVDS TX Signals (Interface to FPGA Fabric)

Signal	Direction	Notes
OUT[*n*-1:0]	Input	Parallel output data where *n* is the serialization factor. A width of 1 bypasses the serializer.
FASTCLK	Input	Fast clock to serialize the data to the LVDS pads.
SLOWCLK	Input	Slow clock to latch the incoming data from the core.

Table 14: LVDS TX Pads

Pad	Direction	Description
TXP	Output	Differential P pad.
TXN	Output	Differential N pad.

The following waveform shows the relationship between the fast clock, slow clock, TX data going to the pad, and byte-aligned data from the core.

Figure 13: LVDS Timing Example Serialization Width of 8

OUT is byte-aligned data passed from the core on the rising edge of SLOWCLK.
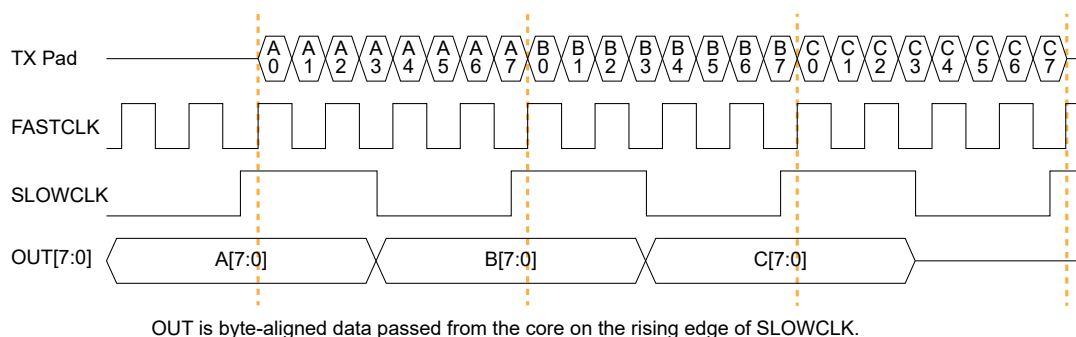
Figure 14: LVDS Timing Data and Clock Relationship Width of 8 (Parallel Clock Division=1)
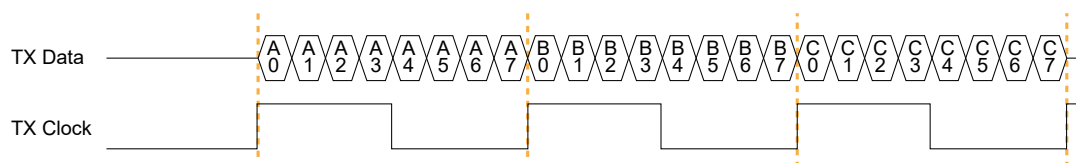
Figure 15: LVDS Timing Data and Clock Relationship Width of 7 (Parallel Clock Division=1)
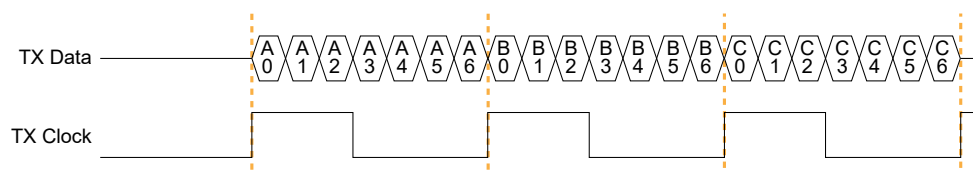
Table 15: LVDS TX Settings in Efinity® Interface Designer

Parameters	Choices	Notes
Mode	serial data output or reference clock output	**serial data output**—Simple output buffer or serialized output. **reference clock output**—Use the transmitter as a clock output. When choosing this mode, the **Serialization Width** you choose should match the serialization for the rest of the LVDS bus.
Parallel Clock Division	1, 2	**1**—The output clock from the LVDS TX lane is parallel clock frequency. **2**—The output clock from the TX lane is half of the parallel clock frequency.
Enable Serialization	On or off	When off, the serializer is bypassed and the LVDS buffer is used as a normal output.
Serialization Width	2, 3, 4, 5, 6, 7, or 8	Supports 8:1, 7:1, 6:1, 5:1, 4:1, 3:1, and 2:1.
Reduce VOD Swing	On or off	When true, enables reduced output swing (similar to slow slew rate).
Output Load	3 (default), 5, 7, or 10	Output load in pF.

LVDS RX

Figure 16: LVDS RX Interface Block Diagram
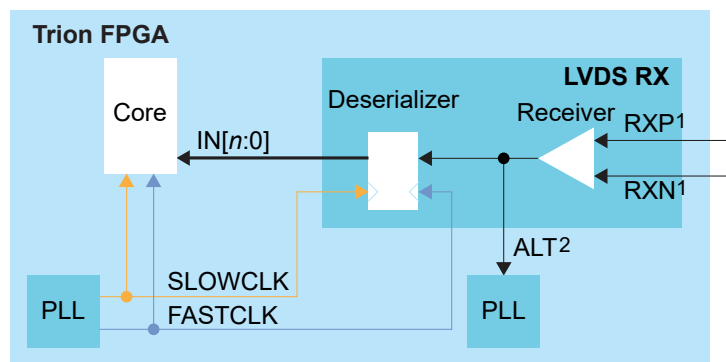
1. There is a ~30k Ω internal weak pull-up to VCCIO (3.3V).
2. Only available for an LVDS RX resource in bypass mode (deserialization width is 1).

Table 16: LVDS RX Signals (Interface to FPGA Fabric)

Signal	Direction	Notes
IN[n-1:0]	Output	Parallel input data where n is the de-serialization factor. A width of 1 bypasses the deserializer.
ALT	Output	Alternative input, only available for an LVDS RX resource in bypass mode (deserialization width is 1; alternate connection type). Alternative connections are PLL_CLKIN and PLL_EXTFB.
FASTCLK	Input	Fast clock to de-serialize the data from the LVDS pads.
SLOWCLK	Input	Slow clock to latch the incoming data to the core.

Table 17: LVDS RX Pads

Pad	Direction	Description
RXP	Input	Differential P pad.
RXN	Input	Differential N pad.

The following waveform shows the relationship between the fast clock, slow clock, RX data coming in from the pad, and byte-aligned data to the core.

*Figure 17: LVDS RX Timing Example Serialization Width of 8*

IN is byte-aligned data passed to the core on the rising edge of SLOWCLK.
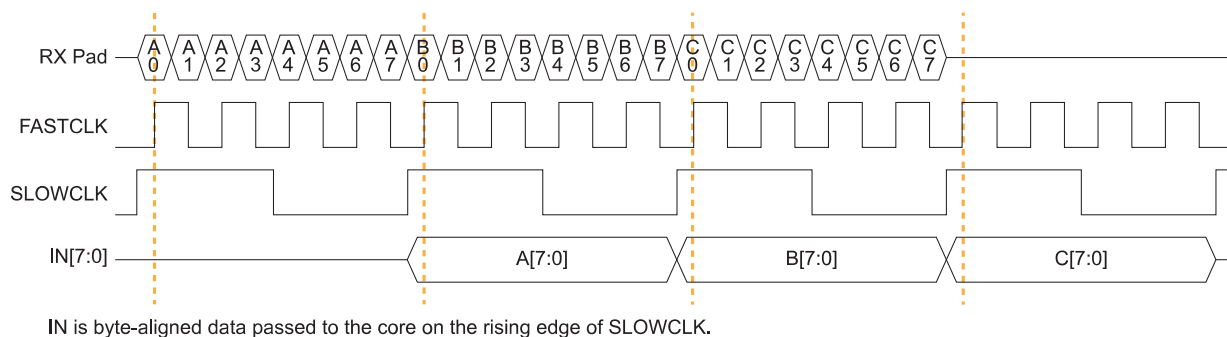
Table 18: LVDS RX Settings in Efinity® Interface Designer

Parameter	Choices	Notes
Connection Type	normal, pll_clkin, pll_extfb	**normal**–Regular RX function. **pll_clkin**–Use the PLL CLKIN alternate function of the LVDS RX resource. **pll_extfb**–Use the PLL external feedback alternate function of the LVDS RX resource.
Enable Deserialization	On or off	When off, the de-serializer is bypassed and the LVDS buffer is used as a normal input.
Deserialization Width	2, 3, 4, 5, 6, 7, or 8	Supports 8:1, 7:1, 6:1, 5:1, 4:1, 3:1, and 2:1.
Enable On-Die Termination	On or off	When on, enables an on-die 100-ohm resistor.

MIPI

The MIPI CSI-2 interface is the most widely used camera interface for mobile.[7]. You can use this interface to build single- or multi-camera designs for a variety of applications.

T13 FPGAs include two hardened MIPI D-PHY blocks (4 data lanes and 1 clock lane) with MIPI CSI-2 IP blocks. The MIPI RX and MIPI TX can operate independently with dedicated I/O banks.

Note: The MIPI D-PHY and CSI-2 controller are hard blocks; users cannot bypass the CSI-2 controller to access the D-PHY directly for non-CSI-2 applications.

The MIPI TX/RX interface supports the MIPI CSI-2 specification v1.3 and the MIPI D-PHY specification v1.1. It has the following features:
- Programmable data lane configuration supporting 1, 2, or 4 lanes
- High-speed mode supports up to 1.5 Gbps data rates per lane
- Operates in continuous and non-continuous clock modes
- 64 bit pixel interface for cameras
- Supports Ultra-Low Power State (ULPS)

Table 19: MIPI Supported Data Types

Supported Data Type	Format
RAW	RAW6, RAW7, RAW8, RAW10, RAW12, RAW14
YUV	YUV420 8-bit (legacy), YUV420 8-bit, YUV420 10-bit, YUV420 8-bit (CSPS), YUV420 10-bit (CSPS), YUV422 8-bit, YUV422 10-bit
RGB	RGB444, RGB555, RGB565, RGB666, RGB888
User Defined	8 bit format

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(7) Source: MIPI Alliance **https://www.mipi.org/specifications/csi-2**

With more than one MIPI TX and RX blocks, Trion® FPGAs support a variety of video applications.

Figure 18: MIPI Example System
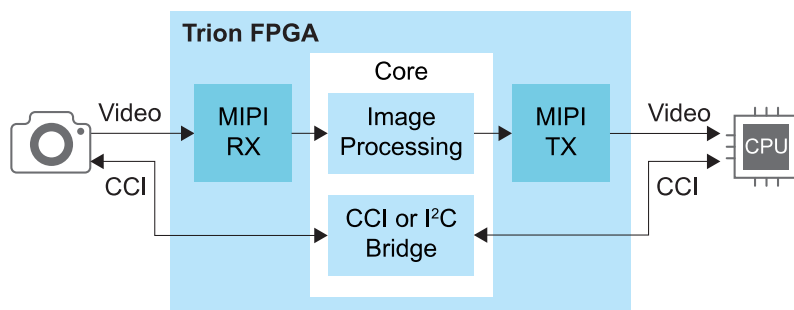
MIPI TX

The MIPI TX is a transmitter interface that translates video data from the Trion® core into packetized data sent over the HSSI interface to the board. Five high-speed differential pin pairs (four data, one clock), each of which represent a lane, connect to the board. Control and video signals connect from the MIPI interface to the core.

Figure 19: MIPI TX x4 Block Diagram
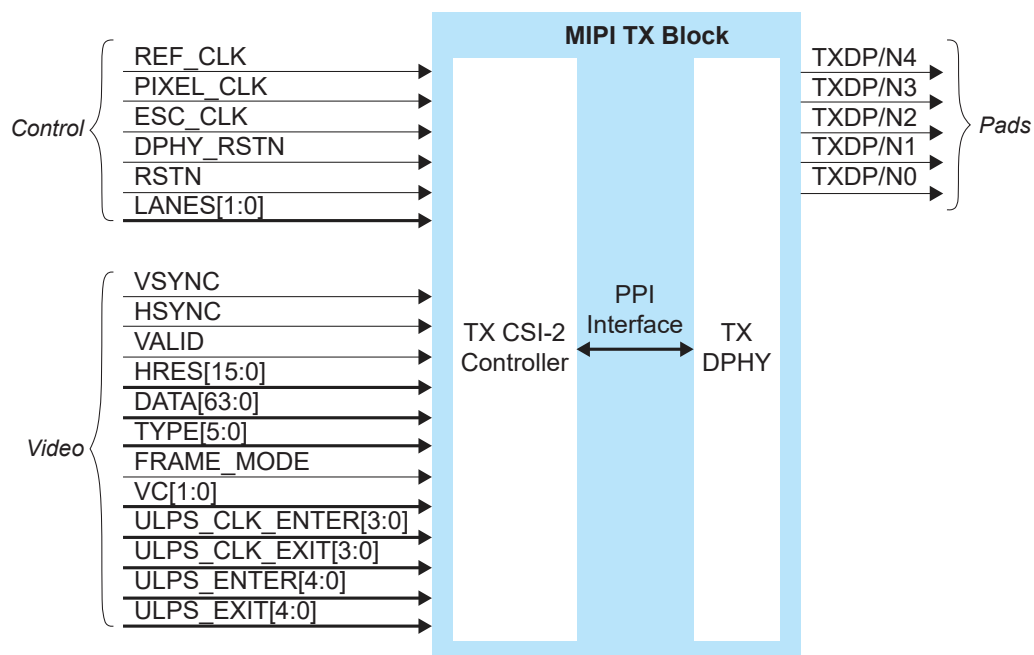
The control signals determine the clocking and how many transceiver lanes are used. All control signals are required except the two reset signals. The reset signals are optional, however, you must use both signals or neither.

The MIPI block requires an escape clock (`ESC_CLK`) for use when the MIPI interface is in escape (low-power) mode, which runs between 11 and 20 MHz.

Note: Efinix recommends that you set the escape clock frequency as close to 20 MHz as possible.

The video signals receive the video data from the core. The MIPI interface block encodes is and sends it out through the MIPI D-PHY lanes.

Figure 20: MIPI TX Interface Block Diagram
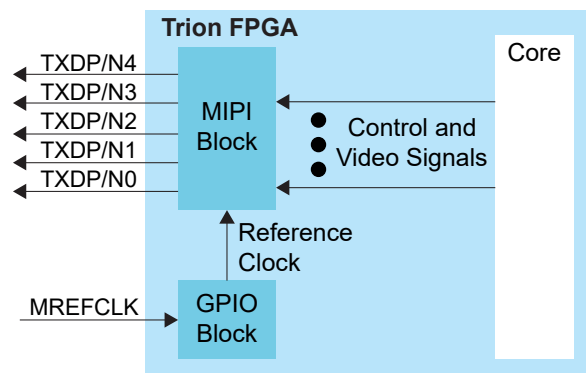
Table 20: MIPI TX Control Signals (Interface to FPGA Fabric)

Signal	Direction	Clock Domain	Description
REF_CLK	Input	N/A	Reference clock for the internal MIPI TX PLL used to generate the transmitted data. The FPGA has a dedicated GPIO resource (MREFCLK) that you must configure to provide the reference clock. All of the MIPI TX blocks share this resource. The frequency is set using Interface Designer configuration options.
PIXEL_CLK	Input	N/A	Clock used for transferring data from the core to the MIPI TX block. The frequency is based on the number of lanes and video format.
ESC_CLK	Input	N/A	Slow clock for escape mode (11 - 20 MHz).
DPHY_RSTN	Input	N/A	(Optional) Reset for the D-PHY logic, active low. Reset with the controller. See **MIPI Reset Timing** on page 43.
RSTN	Input	N/A	(Optional) Reset for the CSI-2 controller logic, active low. Typically, you reset the controller with the PHY (see **MIPI Reset Timing** on page 43). However, when dynamically changing the horizontal resolution, you only need to trigger RSTN (see **TX Requirements for Dynamically Changing the Horizontal Resolution**).
LANES[1:0]	Input	PIXEL_CLK	Determines the number of lanes enabled. Can only be changed during reset. 00: lane 0 01: lanes 0 and 1 11: all lanes

Table 21: MIPI TX Video Signals (Interface to FPGA Fabric)

Signal	Direction	Clock Domain	Description
VSYNC	Input	PIXEL_CLK	Vertical sync.
HSYNC	Input	PIXEL_CLK	Horizontal sync.
VALID	Input	PIXEL_CLK	Valid signal.
HRES[15:0]	Input	PIXEL_CLK	Horizontal resolution. Can only be changed when VSYNC is low, and should be stable for at least one TX pixel clock cycle before VSYNC goes high.
DATA[63:0]	Input	PIXEL_CLK	Video data; the format depends on the data type. New data arrives on every pixel clock.
TYPE[5:0]	Input	PIXEL_CLK	Video data type. Can only be changed when HSYNC is low, and should be stable for at least one TX pixel clock cycle before HSYNC goes high.
FRAME_MODE	Input	PIXEL_CLK	Selects frame format. [8] 0: general frame 1: accurate frame Can only be changed during reset.
VC[1:0]	Input	PIXEL_CLK	Virtual channel (VC). Can only be changed when VSYNC is low, and should be stable at least one TX pixel clock cycle before VSYNC goes high.
ULPS_CLK_ENTER	Input	PIXEL_CLK	Place the clock lane into ULPS mode. Should not be active at the same time as ULPS_CLK_EXIT. Each high pulse should be at least 5 µs.
ULPS_CLK_EXIT	Input	PIXEL_CLK	Remove clock lane from ULPS mode. Should not be active at the same time as ULPS_CLK_ENTER. Each high pulse should be at least 5 µs.
ULPS_ENTER[3:0]	Input	PIXEL_CLK	Place the data lane into ULPS mode. Should not be active at the same time as ULPS_EXIT[3:0]. Each high pulse should be at least 5 µs.
ULPS_EXIT[3:0]	Input	PIXEL_CLK	Remove the data lane from ULPS mode. Should not be active at the same time as ULPS_ENTER[3:0]. Each high pulse should be at least 5 µs.

Table 22: MIPI TX Pads

Pad	Direction	Description
TXDP[4:0]	Output	MIPI transceiver P pads.
TXDN[4:0]	Output	MIPI transceiver N pads.

---

[8] Refer to the MIPI Camera Serial Interface 2 (MIPI CSI-2) for more information about frame formats.

Table 23: MIPI TX Settings in Efinity® Interface Designer

Tab	Parameter	Choices	Notes
Base	PHY Frequency (MHz)	80.00 - 1500.00	Choose one of the possible PHY frequency values.
	Frequency (reference clock)	6, 12, 19.2, 25, 26, 27, 38.4, or 52 MHz	Reference clock frequency.
	Enable Continuous PHY Clocking	On or Off	Turns continuous clock mode on or off.
Control	Escape Clock Pin Name	User defined	
	Invert Escape Clock	On or Off	
	Pixel Clock Pin Name	User defined	
	Invert Pixel Clock	On or Off	
Lane Mapping	TXD0, TXD1, TXD2, TXD3, TXD4	clk, data0, data1, data2, or data3	Map the physical lane to a clock or data lane.
	Clock Timer		
Timing	$T_{CLK-POST}$ $T_{CLK-TRAIL}$ $T_{CLK-PREPARE}$ $T_{CLK-ZERO}$	Varies depending on the PHY frequency	Changes the MIPI transmitter timing parameters per the DPHY specification. Refer to D-PHY Timing Parameters on page 32.
	Escape Clock Frequency (MHz)	User defined	Specify a number between 11 and 20 MHz.
	$T_{CLK-PRE}$	Varies depending on the escape clock frequency	Changes the MIPI transmitter timing parameters per the DPHY specification. Refer to D-PHY Timing Parameters on page 32.
	Data Timer		
	$T_{HS-PREPARE}$ $T_{HS-ZERO}$ $T_{HS-PTRAIL}$	Varies depending on the PHY frequency	Changes the MIPI transmitter timing parameters per the DPHY specification. Refer to D-PHY Timing Parameters on page 32.

MIPI TX Video Data TYPE[5:0] Settings

The video data type can only be changed when HSYNC is low.

Table 24: MIPI TX TYPE[5:0]

TYPE[5:0]	Data Type	Pixel Data Bits per Pixel Clock	Pixels per Clock	Bits per Pixel	Maximum Data Pixels per Line
0x20	RGB444	48	4	12	2,880
0x21	RGB555	60	4	15	2,880
0x22	RGB565	64	4	16	2,880
0x23	RGB666	54	3	18	2,556
0x24	RGB888	48	2	24	1,920
0x28	RAW6	60	10	6	7,680
0x29	RAW7	56	8	7	6,576
0x2A	RAW8	64	8	8	5,760
0x2B	RAW10	60	6	10	4,608
0x2C	RAW12	60	5	12	3,840
0x2D	RAW14	56	4	14	3,288
0x18	YUV420 8 bit	Odd line: 64 Even line: 64	Odd line: 8 Even line: 4	Odd line: 8 Even line: 8, 24	2,880
0x19	YUV420 10 bit	Odd line: 60 Even line: 40	Odd line: 6 Even line: 2	Odd line: 10 Even line: 10, 30	2,304
0x1A	Legacy YUV420 8 bit	48	4	8, 16	3,840
0x1C	YUV420 8 bit (CSPS)	Odd line: 64 Even line: 64	Odd line: 8 Even line: 4	Odd line: 8 Even line: 8, 24	2,880
0x1D	YUV420 10 bit (CSPS)	Odd line: 60 Even line: 40	Odd line: 6 Even line: 2	Odd line: 10 Even line: 10, 30	2,304
0x1E	YUV422 8 bit	64	4	8, 24	2,880
0x1F	YUV422 10 bit	40	2	10, 30	2,304
0x30 - 37	User defined 8 bit	64	8	8	5,760

MIPI RX

The MIPI RX is a receiver interface that translates HSSI signals from the board to video data in the Trion® core. Five high-speed differential pin pairs (one clock, four data), each of which represent a lane, connect to the board. Control, video, and status signals connect from the MIPI interface to the core.

Figure 21: MIPI RX x4 Block Diagram
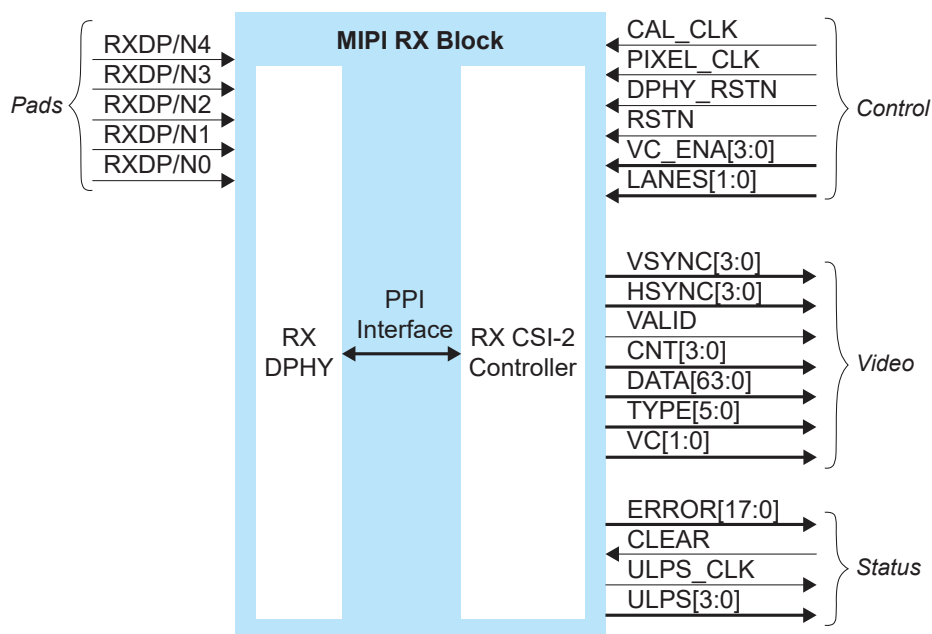
The control signals determine the clocking, how many transceiver lanes are used, and how many virtual channels are enabled. All control signals are required except the two reset signals. The reset signals are optional, however, you must use both signals or neither.

The video signals send the decoded video data to the core. All video signals must fully support the MIPI standard.

The status signals provide optional status and error information about the MIPI RX interface operation.

Figure 22: MIPI RX Interface Block Diagram
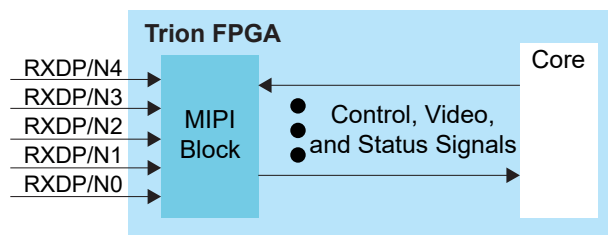
Table 25: MIPI RX Control Signals (Interface to FPGA Fabric)

Signal	Direction	Clock Domain	Notes
CAL_CLK	Input	N/A	Used for D-PHY calibration; must be between 80 and 120 MHz.
PIXEL_CLK	Input	N/A	Clock used for transferring data to the core from the MIPI RX block. The frequency based on the number of lanes and video format.
DPHY_RSTN	Input	N/A	(Optional) Reset for the D-PHY logic, active low. Must be used if RSTN is used. See **MIPI Reset Timing** on page 43.
RSTN	Input	N/A	(Optional) Reset for the CSI-2 controller logic, active low. Must be used if DPHY_RSTN is used. See **MIPI Reset Timing** on page 43.
VC_ENA[3:0]	Input	PIXEL_CLK	Enables different VC channels by setting their index high.
LANES[1:0]	Input	PIXEL_CLK	Determines the number of lanes enabled: 00: lane 0 01: lanes 0 and 1 11: all lanes Can only be set during reset.

Table 26: MIPI RX Video Signals (Interface to FPGA Fabric)

Signal	Direction	Clock Domain	Notes
VSYNC[3:0]	Output	PIXEL_CLK	Vsync bus. High if vsync is active for this VC.
HSYNC[3:0]	Output	PIXEL_CLK	Hsync bus. High if hsync is active for this VC
VALID	Output	PIXEL_CLK	Valid signal.
CNT[3:0]	Output	PIXEL_CLK	Number of valid pixels contained in the pixel data.
DATA[63:0]	Output	PIXEL_CLK	Video data, format depends on data type. New data every pixel clock.
TYPE[5:0]	Output	PIXEL_CLK	Video data type.
VC[1:0]	Output	PIXEL_CLK	Virtual channel (VC).

Table 27: MIPI RX Status Signals (Interface to FPGA Fabric)

Signal	Direction	Signal Interface	Clock Domain	Notes
ERROR[17:0]	Output	IN	PIXEL_CLK	Error bus register. Refer to **Table 28: MIPI RX Error Signals (ERROR[17:0])** on page 29 for details.
CLEAR	Input	OUT	PIXEL_CLK	Reset the error registers.
ULPS_CLK	Output	IN	PIXEL_CLK	High when the clock lane is in the Ultra-Low-Power State (ULPS).
ULPS[3:0]	Output	IN	PIXEL_CLK	High when the lane is in the ULPS mode.

Table 28: MIPI RX Error Signals (ERROR[17:0])

Bit	Name	Description
0	ERR_ESC	Escape Entry Error. Asserted when an unrecognized escape entry command is received.
1	CRC_ERROR_VC0	CRC Error VC0. Set to 1 when a checksum error occurs.
2	CRC_ERROR_VC1	CRC Error VC1. Set to 1 when a checksum error occurs.
3	CRC_ERROR_VC2	CRC Error VC2. Set to 1 when a checksum error occurs.
4	CRC_ERROR_VC3	CRC Error VC3. Set to 1 when a checksum error occurs.
5	HS_RX_TIMEOUT_ERR	HS RX Timeout Error. The protocol should time out when no EoT is received within a certain period in HS RX mode.
6	ECC_1BIT_ERROR	ECC Single Bit Error. Set to 1 when there is a single bit error.
7	ECC_2BIT_ERROR	ECC 2 Bit Error. Set to 1 if there is a 2 bit error in the packet.
8	ECCBIT_ERROR	ECC Error. Asserted when an error exists in the ECC.
9	ECC_NO_ERROR	ECC No Error. Asserted when an ECC is computed with a result zero. This bit is high when the receiver is receiving data correctly.
10	FRAME_SYNC_ERROR	Frame Sync Error. Asserted when a frame end is not paired with a frame start on the same virtual channel.
11	INVLD_PKT_LEN	Invalid Packet Length. Set to 1 if there is an invalid packet length.
12	INVLD_VC	Invalid VC ID. Set to 1 if there is an invalid CSI VC ID.
13	INVALID_DATA_TYPE	Invalid Data Type. Set to 1 if the received data is invalid.
14	ERR_FRAME	Error In Frame. Asserted when VSYNC END received when CRC error is present in the data packet.
15	CONTROL_ERR	Control Error. Asserted when an incorrect line state sequence is detected.
16	SOT_ERR	Start-of-Transmission (SoT) Error. Corrupted high-speed SoT leader sequence while proper synchronization can still be achieved.
17	SOT_SYNC_ERR	SoT Synchronization Error. Corrupted high-speed SoT leader sequence while proper synchronization cannot be expected.

Table 29: MIPI RX Pads

Pad	Direction	Description
RXDP[4:0]	Input	MIPI transceiver P pads.
RXDN[4:0]	Input	MIPI transceiver N pads.

Table 30: MIPI RX Settings in Efinity® Interface Designer

Tab	Parameter	Choices	Notes
Control	DPHY Calibration Clock Pin Name	User defined	
	Invert DPHY Calibration Clock	On or Off	
	Pixel Clock Pin Name	User defined	
	Invert Pixel Clock	On or Off	
Status	Enable Status	On or Off	Indicate whether you want to use the status pins.
Lane Mapping	RXD0, RXD1, RXD2, RXD3, RXD4	clk, data0, data1, data2, or data3	Map the physical lane to a clock or data lane.
	Swap P&N Pin	On or Off	Reverse the P and N pins for the physical lane.
Timing	Calibration Clock Freq (MHz)	User defined	Specify a number between 80 and 120 MHz.
	Clock Timer ($T_{CLK\text{-}SETTLE}$)	40 - 2,590 ns	Changes the MIPI receiver timing parameters per the DPHY specification. Refer to D-PHY Timing Parameters on page 32.
	Data Timer ($T_{HS\text{-}SETTLE}$)	40 - 2,590 ns	Changes the MIPI receiver timing parameters per the DPHY specification. Refer to D-PHY Timing Parameters on page 32.

MIPI RX Video Data TYPE[5:0] Settings

The video data type can only be changed when HSYNC is low.

Table 31: MIPI RX TYPE[5:0]

TYPE[5:0]	Data Type	Pixel Data Bits per Pixel Clock	Pixels per Clock	Bits per Pixel	Maximum Data Pixels per Line
0x20	RGB444	48	4	12	2,880
0x21	RGB555	60	4	15	2,880
0x22	RGB565	64	4	16	2,880
0x23	RGB666	54	3	18	2,556
0x24	RGB888	48	2	24	1,920
0x28	RAW6	48	8	6	7,680
0x29	RAW7	56	8	7	6,576
0x2A	RAW8	64	8	8	5,760
0x2B	RAW10	40	4	10	4,608
0x2C	RAW12	48	4	12	3,840
0x2D	RAW14	56	4	14	3,288
0x18	YUV420 8 bit	Odd line: 64 Even line: 64	Odd line: 8 Even line: 4	Odd line: 8 Even line: 8, 24	2,880
0x19	YUV420 10 bit	Odd line: 40 Even line: 40	Odd line: 4 Even line: 2	Odd line: 10 Even line: 10, 30	2,304
0x1A	Legacy YUV420 8 bit	48	4	8, 16	3,840
0x1C	YUV420 8 bit (CSPS)	Odd line: 64 Even line: 64	Odd line: 8 Even line: 4	Odd line: 8 Even line: 8, 24	2,880
0x1D	YUV420 10 bit (CSPS)	Odd line: 40 Even line: 40	Odd line: 4 Even line: 2	Odd line: 10 Even line: 10, 30	2,304
0x1E	YUV422 8 bit	64	4	8, 24	2,880
0x1F	YUV422 10 bit	40	2	10, 30	2,304
0x30 - 37	User defined 8 bit	64	8	8	5,760

D-PHY Timing Parameters

During CSI-2 data transmission, the MIPI D-PHY alternates between low power mode and high-speed mode. The D-PHY specification defines timing parameters to facilitate the correct hand-shaking between the MIPI TX and MIPI RX during mode transitions.

You set the timing parameters to correspond to the specifications of your hardware in the Efinity® Interface Designer.

- *RX parameters*—$T_{CLK-SETTLE}$, $T_{HS-SETTLE}$ (see **Table 25: MIPI RX Control Signals (Interface to FPGA Fabric)** on page 28)
- *TX parameters*—$T_{CLK-POST}$, $T_{CLK-TRAIL}$, $T_{CLK-PREPARE}$, $T_{CLK-ZERO}$, $T_{CLK-PRE}$, $T_{HS-PREPARE}$, $T_{HS-ZERO}$, $T_{HS-TRAIL}$ (see **Table 23: MIPI TX Settings in Efinity Interface Designer** on page 25)

Figure 23: High-Speed Data Transmission in Bursts Waveform
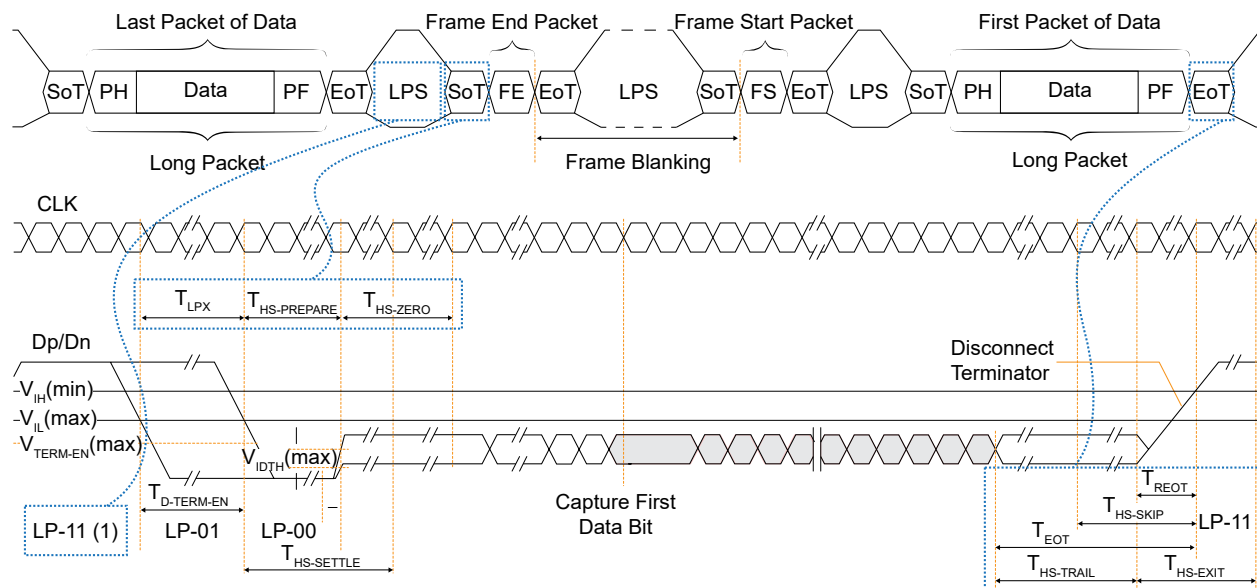
Note:
1. To enter high-speed mode, the D-PHY goes through states LP-11, LP-01, and LP-00. The D-PHY generates LP-11 to exit high-speed mode.

Figure 24: Switching the Clock Lane between Clock Transmission and Low Power Mode Waveform

Table 32: D-PHY Timing Specifications

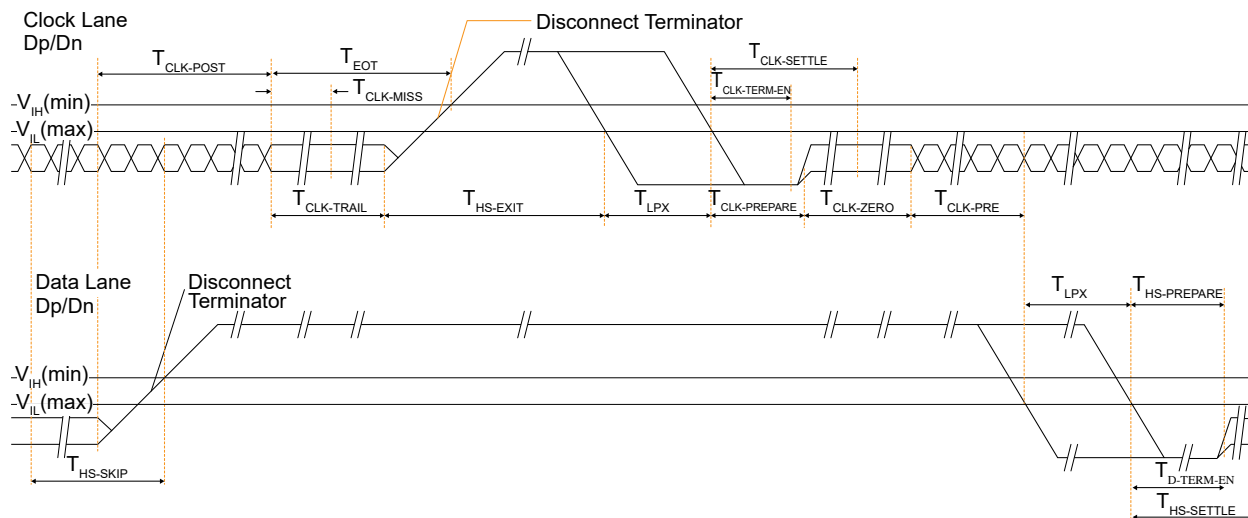| Parameter	Description	Min	Typ	Max	Unit
$T_{CLK\text{-}POST}$	Time that the transmitter continues to send HS clock after the last associated Data Lane has transitioned to LP Mode. Interval is defined as the period from the end of $T_{HS\text{-}TRAIL}$ to the beginning of $T_{CLK\text{-}TRAIL}$.	60 ns + 52*UI	–	–	ns
$T_{CLK\text{-}PRE}$	Time that the HS clock shall be driven by the transmitter prior to any associated Data Lane beginning the transition from LP to HS mode.	8	–	–	UI
$T_{CLK\text{-}PREPARE}$	Time that the transmitter drives the Clock Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission.	38	–	95	ns
$T_{CLK\text{-}SETTLE}$	Time interval during which the HS receiver should ignore any Clock Lane HS transitions, starting from the beginning of $T_{CLK\text{-}PREPARE}$.	95	–	300	ns
$T_{CLK\text{-}TRAIL}$	Time that the transmitter drives the HS-0 state after the last payload clock bit of a HS transmission burst.	60	–	–	ns
$T_{CLK\text{-}PREPARE}$ + $T_{CLK\text{-}ZERO}$	$T_{CLK\text{-}PREPARE}$ + time that the transmitter drives the HS-0 state prior to starting the Clock.	300	–	–	ns
$T_{HS\text{-}PREPARE}$	Time that the transmitter drives the Data Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission	40 ns + 4*UI	–	85 ns + 6*UI	ns
$T_{HS\text{-}SETTLE}$	Time interval during which the HS receiver shall ignore any Data Lane HS transitions, starting from the beginning of $T_{HS\text{-}PREPARE}$. The HS receiver shall ignore any Data Lane transitions before the minimum value, and the HS receiver shall respond to any Data Lane transitions after the maximum value.	85 ns + 6*UI	–	145 ns + 10*UI	ns
$T_{HS\text{-}TRAIL}$	Time that the transmitter drives the flipped differential state after last payload data bit of a HS transmission burst	max(n*8*UI, 60 ns + n*4*UI)	–	–	ns
T_{LPX}	Transmitted length of any Low-Power state period	50	–	–	ns
$T_{HS\text{-}PREPARE}$ + $T_{HS\text{-}ZERO}$	$T_{HS\text{-}PREPARE}$ + time that the transmitter drives the HS-0 state prior to transmitting the Sync sequence.	145 ns + 10*UI	–	–	ns

Power Up Sequence

Efinix® recommends the following power up sequence when powering Trion® FPGAs:

1. Power up VCC and VCCA_*xx* first.
2. When VCC and VCCA_*xx* are stable, power up all VCCIO pins. There is no specific timing delay between the VCCIO pins.
3. Apply power to VCC12A_MIPI_TX, VCC12A_MIPI_RX, and VCC25A_MIPI at least t$_{MIPI\_POWER}$ after VCC is stable.
4. After all power supplies are stable, hold CRESET_N low for a duration of t$_{CRESET\_N}$ before asserting CRESET_N from low to high to trigger active SPI programming (the FPGA loads the configuration data from an external flash device).

When you are not using the GPIO, MIPI or PLL instances, connect the pins as shown in the following table.

Table 33: Connection Requirements for Unused Instances

Unused Instance	Pin	Note
GPIO	VCCIOxx	Connect to either 1.8 V, 2.5 V, or 3.3 V.
PLL	VCCA_PLL	Connect to VCC.
MIPI	VCC12A_MIPI_TX	Connect to VCC.
	VCC12A_MIPI_RX	Connect to VCC.
	VCC25A_MIPI	Connect to VCC.

Note: Refer to Configuration Timing on page 44 and MIPI Power-Up Timing on page 43 for timing information.

Figure 25: Trion® FPGAs Power Up Sequence
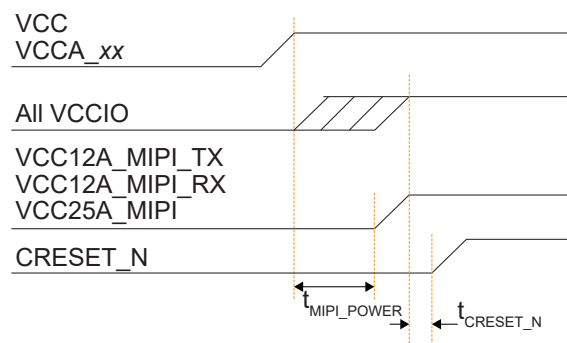
Power Supply Current Transient

You may observe an inrush current on the dedicated power rail during power-up. You must ensure that the power supplies selected in your board meets the current requirement during power-up and the estimated current during user mode. Use the Power Estimator to calculate the estimated current during user mode.

Table 34: Maximum Power Supply Current Transient

Power Supply	Maximum Power Supply Current Transient[9][10]	Unit
VCC	35	mA

Configuration

The T13 FPGA contains volatile Configuration RAM (CRAM). The user must configure the CRAM for the desired logic function upon power-up and before the FPGA enters normal operation. The FPGA's control block manages the configuration process and uses a bitstream to program the CRAM. The Efinity® software generates the bitstream, which is design dependent. You can configure the T13 FPGA(s) in active, passive, or JTAG mode.

Learn more: Refer to **AN 006: Configuring Trion FPGAs** for details on the dedicated configuration pins and how to configure FPGA(s).

Figure 26: High-Level Configuration Options
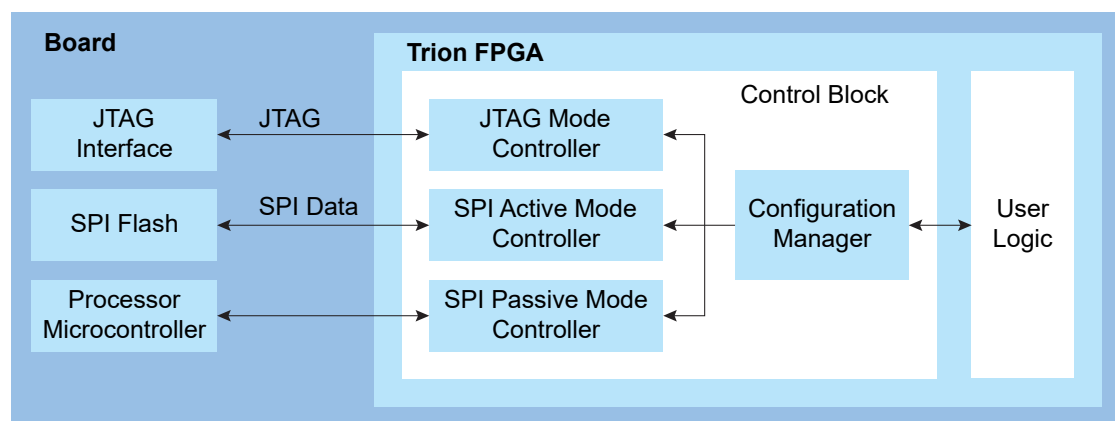
In active mode, the FPGA controls the configuration process. An oscillator circuit within the FPGA provides the configuration clock. The bitstream is typically stored in an external serial flash device, which provides the bitstream when the FPGA requests it.

The control block sends out the instruction and address to read the configuration data. First, it issues a release from power-down instruction to wake up the external SPI flash. Then, it waits for at least 30 μs before issuing a fast read command to read the content of SPI flash from address 24h'000000.

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[9] Inrush current for other power rails are not significant in Trion® FPGAs.
[10] Measured at room temperature.

In passive mode, the FPGA is the slave and relies on an external master to provide the control, bitstream, and clock for configuration. Typically the master is a microcontroller or another FPGA in active mode.

In JTAG mode, you configure the FPGA via the JTAG interface.

Supported Configuration Modes

Table 35: T13 Configuration Modes by Package

Configuration Mode	Width	BGA256	BGA169
Active	x1	✓	✓
	x2	✓	✓
	x4	✓	✓
Passive	x1	✓	✓
	x2	✓	✓
	x4	✓	✓
	x8	✓	
	x16	✓	
	x32	✓	
JTAG	x1	✓	✓

Learn more: Refer to **AN 006: Configuring Trion FPGAs** for more information.

Mask-Programmable Memory Option

The T13 FPGA is equipped with one-time programmable MPM. With this feature, you use on-chip MPM instead of an external serial flash device to configure the FPGA. This option is for systems that require an ultra-small factor and the lowest cost structure such that an external serial flash device is undesirable and/or not required at volume production. MPM is a one-time factory programmable option that requires a Non-Recurring Engineering (NRE) payment. To enable MPM, submit your design to our factory; our Applications Engineers (AEs) convert your design into a single configuration mask to be specially fabricated.

DC and Switching Characteristics

Table 36: Absolute Maximum Ratings

Conditions beyond those listed may cause permanent damage to the device. Device operation at the absolute maximum ratings for extended periods of time has adverse effects on the device.

Symbol	Description	Min	Max	Units
VCC	Core power supply	-0.5	1.42	V
VCCIO	I/O bank power supply	-0.5	4.6	V
VCCA_PLL	PLL analog power supply	-0.5	1.42	V
VCC25A_MIPI0 VCC25A_MIPI1	2.5 V analog power supply for MIPI	-0.5	2.75	V
VCC12A_MIPI0_TX VCC12A_MIPI1_TX	1.2 V TX analog power supply for MIPI	-0.5	1.42	V
VCC12A_MIPI0_RX VCC12A_MIPI1_RX	1.2 V RX analog power supply for MIPI	-0.5	1.42	V
V_{IN}	I/O input voltage	-0.5	4.6	V
T_J	Operating junction temperature	-40	125	°C

Table 37: Recommended Operating Conditions (C3, C4, Q4, and I4 Speed Grades) [11]

Symbol	Description	Min	Typ	Max	Units
VCC	Core power supply	1.15	1.2	1.25	V
VCCIO	1.8 V I/O bank power supply	1.71	1.8	1.89	V
	2.5 V I/O bank power supply	2.38	2.5	2.63	V
	3.3 V I/O bank power supply	3.14	3.3	3.47	V
VCCA_PLL	PLL analog power supply	1.15	1.2	1.25	V
VCC25A_MIPI0 VCC25A_MIPI1	2.5 V analog power supply for MIPI	2.38	2.5	2.63	V
VCC12A_MIPI0_TX VCC12A_MIPI1_TX	1.2 V TX analog power supply for MIPI	1.15	1.2	1.25	V
VCC12A_MIPI0_RX VCC12A_MIPI1_RX	1.2 V RX analog power supply for MIPI	1.15	1.2	1.25	V
V_{IN}	I/O input voltage[12]	-0.3	–	VCCIO + 0.3	V
T_{JCOM}	Operating junction temperature, commercial	0	–	85	°C
T_{JIND}	Operating junction temperature, industrial	-40	–	100	°C
T_{JAUT}	Operating junction temperature, automotive	-40	–	105	°C

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[11] Supply voltage specification applied to the voltage taken at the device pins with respect to ground, not at the power supply.
[12] Values applicable to both input and tri-stated output configuration.

Table 38: Recommended Operating Conditions (C4L and I4L Speed Grades) [11]

Symbol	Description	Min	Typ	Max	Units
VCC	Core power supply	1.05	1.1	1.15	V
VCCIO	1.8 V I/O bank power supply	1.71	1.8	1.89	V
	2.5 V I/O bank power supply	2.38	2.5	2.63	V
	3.3 V I/O bank power supply	3.14	3.3	3.47	V
VCCA_PLL	PLL analog power supply	1.05	1.1	1.15	V
VCC25A_MIPI0 VCC25A_MIPI1	2.5 V analog power supply for MIPI	2.38	2.5	2.63	V
VCC12A_MIPI0_TX VCC12A_MIPI1_TX	1.1 V TX analog power supply for MIPI	1.05	1.1	1.15	V
VCC12A_MIPI0_RX VCC12A_MIPI1_RX	1.1 V RX analog power supply for MIPI	1.05	1.1	1.15	V
V_{IN}	I/O input voltage[13]	-0.3	–	VCCIO + 0.3	V
T_{JCOM}	Operating junction temperature, commercial	0	–	85	°C
T_{JIND}	Operating junction temperature, industrial	-40	–	100	°C

Table 39: Power Supply Ramp Rates

Symbol	Description	Min	Max	Units
t_{RAMP}	Power supply ramp rate for all supplies.	0.01	10	V/ms

Table 40: Single-Ended I/O DC Electrical Characteristics

I/O Standard	V_{IL} (V)		V_{IH} (V)		V_{OL} (V)	V_{OH} (V)
	Min	Max	Min	Max	Max	Min
3.3 V LVCMOS	-0.3	0.8	2	VCCIO + 0.3	0.2	VCCIO - 0.2
3.3 V LVTTL	-0.3	0.8	2	VCCIO + 0.3	0.4	2.4
2.5 V LVCMOS	-0.3	0.7	1.7	VCCIO + 0.3	0.5	1.8
1.8 V LVCMOS	-0.3	0.35 * VCCIO	0.65 * VCCIO	VCCIO + 0.3	0.45	VCCIO - 0.45

Table 41: Single-Ended I/O and Dedicated Configuration Pins Schmitt Trigger Buffer Characteristic

Voltage (V)	VT+ (V) Schmitt Trigger Low-to-High Threshold	VT- (V) Schmitt Trigger High-to-Low Threshold	Input Leakage Current (µA)	Tri-State Output Leakage Current (µA)
3.3	1.73	1.32	±10	±10
2.5	1.37	1.01	±10	±10
1.8	1.05	0.71	±10	±10

---

[13] Values applicable to both input and tri-stated output configuration.

Table 42: Single-Ended I/O Buffer Drive Strength Characteristics

Junction temperature at T_J = 25 °C, power supply at nominal voltage.

I/O Standard	3.3 V		2.5 V		1.8 V	
Drive Strength	I_{OH} (mA)	I_{OL} (mA)	I_{OH} (mA)	I_{OL} (mA)	I_{OH} (mA)	I_{OL} (mA)
1	14.4	8.0	9.1	8.0	4.4	5.1
2	19.1	10.5	12.2	10.5	5.8	6.8
3	23.9	13.3	15.2	13.4	7.3	8.6
4	28.7	15.8	18.2	15.9	8.6	10.3

Table 43: Single-Ended I/O Internal Weak Pull-Up and Pull-Down Resistors

I/O Standard	Internal Pull-Up			Internal Pull-Down			Units
	Min	Typ	Max	Min	Typ	Max	
3.3 V LVTTL/LVCMOS	27	40	65	30	47	83	kΩ
2.5 V LVCMOS	35	55	95	37	62	118	kΩ
1.8 V LVCMOS	53	90	167	54	99	202	kΩ

Table 44: LVDS Pins Configured as Single-Ended I/O DC Electrical Characteristics

I/O Standard	V_{IL} (V)		V_{IH} (V)		V_{OL} (V)	V_{OH} (V)
	Min	Max	Min	Max	Max	Min
3.3 V LVCMOS	-0.3	0.8	2	VCCIO + 0.3	0.2	VCCIO - 0.2
3.3 V LVTTL	-0.3	0.8	2	VCCIO + 0.3	0.4	2.4

Table 45: LVDS Pins Configured as Single-Ended I/O DC Electrical Characteristics

Voltage (V)	Input Leakage Current (µA)	Tri-State Output Leakage Current (µA)
3.3	±10	±10

Table 46: LVDS Pins as Single-Ended I/O Buffer Drive Strength Characteristics

Junction temperature at T_J = 25 °C, power supply at nominal voltage, device in nominal process (TT).

I/O Standard	Drive Strength	
	I_{OH} (mA)	I_{OL} (mA)
3.3 V	37.6	22

Table 47: LVDS Pins Configured as Single-Ended I/O Internal Weak Pull-Up Resistors

I/O Standard	Internal Pull-Up			Units
	Min	Typ	Max	
3.3 V LVTTL/LVCMOS	27	40	65	kΩ

Table 48: Single-Ended I/O and LVDS Pins Configured as Single-Ended I/O Characteristics

Symbol	Description	All Speed Grades	Units
f_{MAX}	Single-ended I/O and LVDS configured as single-ended I/O maximum frequency. Test condition at 10 pF output loading. Applicable to all I/O standards.	200	MHz

Table 49: Block RAM Characteristics

Symbol	Description	Speed Grade		Units
		C3, C4L, I4L	C4, I4, Q4	
f_{MAX}	Block RAM maximum frequency.	310	400	MHz

Table 50: Multiplier Block Characteristics

Symbol	Description	Speed Grade		Units
		C3, C4L, I4L	C4, I4, Q4	
f_{MAX}	Multiplier block maximum frequency.	310	400	MHz

LVDS I/O Electrical and Timing Specifications

The LVDS pins comply with the EIA/TIA electrical specifications.

ⓘ **Note:** The LVDS RX supports the sub-lvds, slvs, HiVcm, RSDS and 3.3 V LVPECL differential I/O standards with a transfer rate of up to 800 Mbps.

Table 51: LVDS I/O Electrical Specifications

Parameter	Description	Test Conditions	Min	Typ	Max	Unit
V_{CCIO}	LVDS I/O Supply Voltage	–	2.97	3.3	3.63	V
LVDS TX						
V_{OD}	Output Differential Voltage	–	250	–	450	mV
ΔV_{OD}	Change in V_{OD}	–	–	–	50	mV
V_{OCM}	Output Common Mode Voltage	RT = 100 Ω	1,125	1,250	1,375	mV
ΔV_{OCM}	Change in V_{OCM}	–	–	–	50	mV
V_{OH}	Output High Voltage	RT = 100 Ω	–	–	1475	mV
V_{OL}	Output Low Voltage	RT = 100 Ω	925	–	–	mV
I_{SAB}	Output Short Circuit Current	–	–	–	24	mA
LVDS RX						
V_{ID}	Input Differential Voltage	–	100	–	600	mV
V_{ICM}	Input Common Mode Voltage	–	100	–	2,000	mV
V_{TH}	Differential Input Threshold	–	-100	–	100	mV
I_{IL}	Input Leakage Current	–	–	–	20	µA

Figure 27: LVDS RX I/O Electrical Specification Waveform
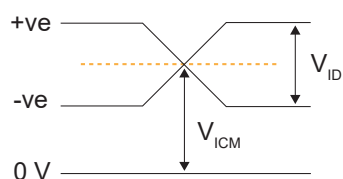
Table 52: LVDS Timing Specifications

Parameter	Description	Min	Typ	Max	Unit
t_{LVDS_DT}	LVDS TX reference clock output duty cycle	45	50	55	%
t_{LVDS_skew}	LVDS TX lane-to-lane skew	–	200	–	ps

ESD Performance

Refer to the Trion Reliability Report for ESD performance data.

MIPI Electrical Specifications and Timing

The MIPI D-PHY transmitter and receiver are compliant to the MIPI Alliance Specification for D-PHY Revision 1.1.

Table 53: High–Speed MIPI D–PHY Transmitter (TX) DC Specifications

Parameter	Description	Min	Typ	Max	Unit
V_{CMTX}	High–speed transmit static common–mode voltage	150	200	250	mV
$|\Delta V_{CMTX(1,0)}|$	V_{CMTX} mismatch when output is Differential–1 or Differential–0	–	–	5	mV
$|V_{OD}|$	High–speed transmit differential voltage	140	200	270	mV
$|\Delta V_{CMTX}|$	VOD mismatch when output is Differential–1 or Differential–0	–	–	14	mV
V_{OHHS}	High–speed output high voltage	–	–	360	mV
Z_{OS}	Single ended output impedance	40	50	62.5	Ω
ΔZ_{OS}	Single ended output impedance mismatch	–	–	10	%

Table 54: Low–Power MIPI D–PHY Transmitter (TX) DC Specifications

Parameter	Description	Min	Typ	Max	Unit
V_{OH}	Thevenin output high level	0.99	–	1.21	V
V_{OL}	Thevenin output low level	–50	–	50	mV
Z_{OLP}	Output impedance of low–power transmitter	110	–	–	Ω

Table 55: High–Speed MIPI D–PHY Receiver (RX) DC Specifications

Parameter	Description	Min	Typ	Max	Unit
$V_{CMRX(DC)}$	Common mode voltage high-speed receive mode	70	–	330	mV
V_{IDTH}	Differential input high threshold	–	–	70	mV
V_{IDTL}	Differential input low threshold	–70	–	–	mV
V_{IHHS}	Single-ended input high voltage	–	–	460	mV
V_{ILHS}	Single-ended input low voltage	–40	–	–	mV
$V_{TERM-EN}$	Single-ended threshold for high–speed termination enable	–	–	450	mV
Z_{ID}	Differential input impedance	80	100	125	Ω

Table 56: Low–Power MIPI D–PHY Receiver (RX) DC Specifications

Parameter	Description	Min	Typ	Max	Unit
V_{IH}	Logic 1 input voltage	880	–	–	mV
V_{IL}	Logic 0 input voltage, not in ULP state	–	–	550	mV
$V_{IL-ULPS}$	Logic 0 input voltage, ULP state	–	–	300	mV
V_{HYST}	Input hysteresis	25	–	–	mV

MIPI Power-Up Timing

Apply power to VCC12A_MIPI_TX, VCC12A_MIPI_RX, and VCC25A_MIPI at least t_{MIPI_POWER} after VCC is stable. See **Power Up Sequence** on page 34 for a power-up sequence diagram.

Table 57: MIPI Timing

Symbol	Parameter	Min	Typ	Max	Units
t_{MIPI_POWER}	Minimum time after VCC and VCCA_*xx* are stable before powering VCC12A_MIPI_TX, VCC12A_MIPI_RX, and VCC25A_MIPI.	1	–	–	µs

MIPI Reset Timing

The MIPI RX and TX interfaces have two signals (RSTN and DPHY_RSTN) to reset the CSI-2 and D-PHY controller logic. These signals are active low, and you should use them together to reset the MIPI interface.

The following waveform illustrates the minimum time required to reset the MIPI interface.
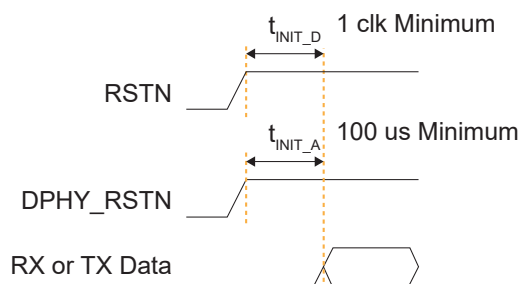
Figure 28: RSTN and DPHY_RSTN Timing Diagram

Table 58: MIPI Timing

Symbol	Parameter	Min	Typ	Max	Units
t_{INIT_A}	Minimum time between the rising edge of DPHY_RSTN and the start of MIPI RX or TX data.	100	–	–	µs
t_{INIT_D}	Minimum time between the rising edge of RSTN and the start of MIPI RX or TX data.	1	–	–	clk

Configuration Timing

The T13 FPGA has the following configuration timing specifications. Refer to **AN 006: Configuring Trion FPGAs** for detailed configuration information.

Timing Waveforms

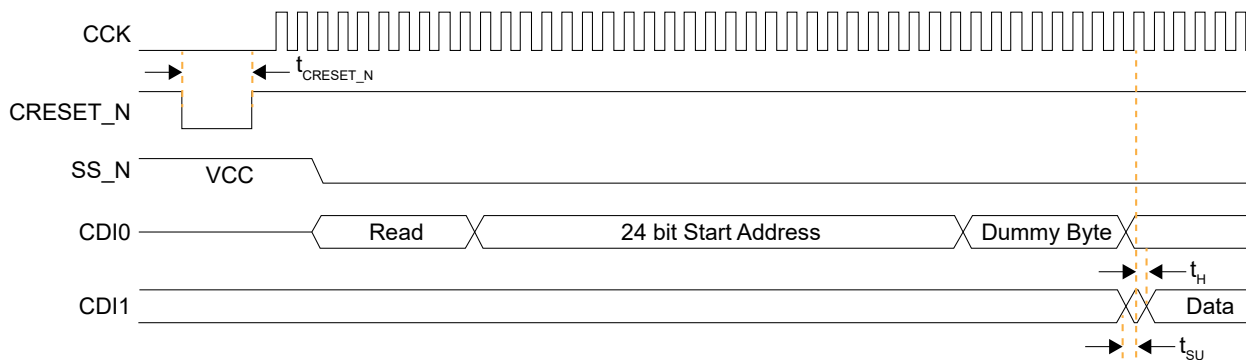*Figure 29: SPI Active Mode (x1) Timing Sequence*
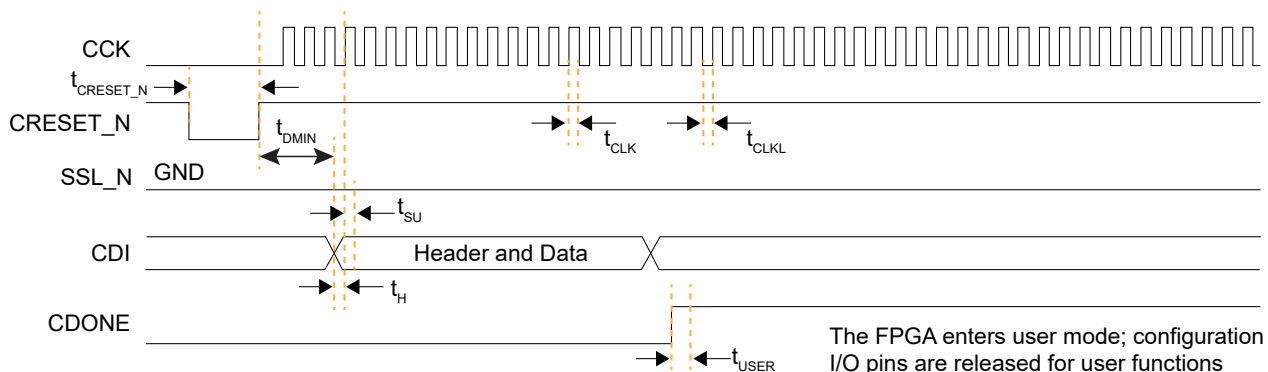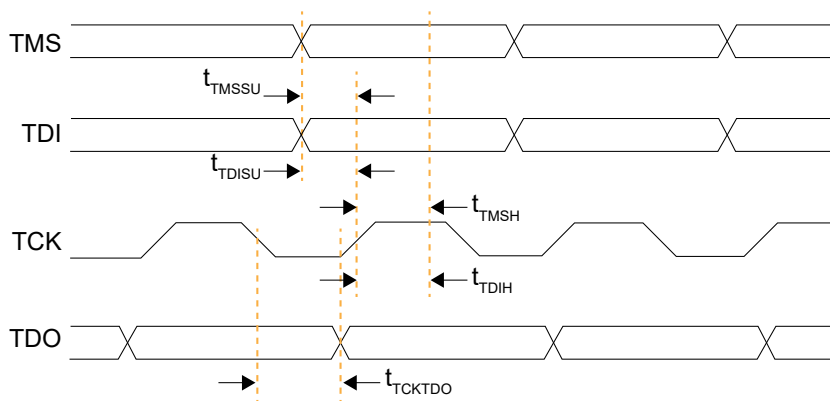

Figure 30: SPI Passive Mode (x1) Timing Sequence

Figure 31: Boundary-Scan Timing Waveform

Timing Parameters

Table 59: All Modes

Symbol	Parameter	Min	Typ	Max	Units
t_{CRESET_N}	Minimum creset_n low pulse width required to trigger re-configuration.	320	–	–	ns
t_{USER}	Minimum configuration duration after CDONE goes high before entering user mode.[14][15] Test condition at 10 kΩ pull-up resistance and 10 pF output loading on CDONE pin.	12	–	–	µs

Table 60: Active Mode

Symbol	Parameter	Frequency	Min	Typ	Max	Units
f_{MAX_M}	Active mode configuration clock frequency.	DIV4	14	20	26	MHz
		DIV8	7	10	13	MHz
t_{SU}	Setup time. Test condition at 3.3 V I/O standard and 0 pF output loading.	–	7.5	–	–	ns
t_H	Hold time. Test condition at 3.3 V I/O standard and 0 pF output loading.	–	1	–	–	ns

Table 61: Passive Mode

Symbol	Parameter	Min	Typ	Max	Units
f_{MAX_S}	Passive mode X1 configuration clock frequency.	–	–	25	MHz
	Passive mode X2, X4 or X8 configuration clock frequency.	–	–	50	MHz
t_{CLKH}	Configuration clock pulse width high.	4.8	–	–	ns
t_{CLKL}	Configuration clock pulse width low.	4.8	–	–	ns
t_{SU}	Setup time.	6	–	–	ns
t_H	Hold time.	1	–	–	ns
t_{DMIN}	Minimum time between deassertion of CRESET_N to first valid configuration data.	1.2	–	–	µs

---

[14] The FPGA may go into user mode before t_{USER} has elapsed. However, Efinix recommends that you keep the system interface to the FPGA in reset until t_{USER} has elapsed.

[15] For JTAG programming, the min t_{USER} configuration time is required after CDONE goes high and FPGA receives the ENTERUSER instruction from JTAG host (TAP controller in UPDATE_IR state).

Table 62: JTAG Mode

Symbol	Parameter	Min	Typ	Max	Units
f_{TCK}	TCK frequency.	–	–	33	MHz
t_{TDISU}	TDI setup time.	3.5	–	–	ns
t_{TDIH}	TDI hold time.	1	–	–	ns
t_{TMSSU}	TMS setup time.	3	–	–	ns
t_{TMSH}	TMS hold time.	1	–	–	ns
t_{TCKTDO}	TCK falling edge to TDO output.	–	–	10.5[16]	ns

PLL Timing and AC Characteristics

The following tables describe the PLL timing and AC characteristics.

Table 63: PLL Timing

Symbol	Parameter	Min	Typ	Max	Units
F_{IN}[17]	Input clock frequency from core.	10	–	330	MHz
	Input clock frequency from GPIO.	10	–	200	MHz
	Input clock frequency from LVDS.	10	–	400	MHz
F_{OUT}	Output clock frequency.	0.24	–	500	MHz
F_{VCO}	PLL VCO frequency.	500	–	1,600	MHz
F_{PFD}	Phase frequency detector input frequency.	10	–	50	MHz

Table 64: PLL AC Characteristics[18]

Symbol	Parameter	Min	Typ	Max	Units
t_{DT}	Output clock duty cycle.	40	50	60	%
t_{OPJIT} (PK - PK) [19]	Output clock period jitter (PK-PK).	–	–	200	ps
t_{ILJIT} (PK - PK)	Input clock long-term jitter (PK-PK)	–	–	800	ps
t_{LOCK}	PLL lock-in time.	–	–	0.5	ms

---

[16] 0 pf output loading.
[17] When using the Dynamic clock source mode, the maximum input clock frequency is limited by the slowest clock frequency of the assigned clock source. For example, the maximum input clock frequency of a Dynamic clock source mode from core and GPIO is 200 MHz.
[18] Test conditions at 3.3 V and room temperature.
[19] The output jitter specification applies to the PLL jitter when an input jitter of 20 ps is applied.

Pinout Description

The following tables describe the pinouts for power, ground, configuration, and interfaces.

Table 65: General Pinouts

Function	Group	Direction	Description
VCC	Power	–	Core power supply.
VCCA_*xx*	Power	–	PLL analog power supply. *xx* indicates location: TL: Top left, TR: Top right, BR: bottom right
VCCIO*xx*	Power	–	I/O pin power supply. *xx* indicates the bank location: 1A: Bank 1A, 3E: Bank 3E 4A: Bank 4A (only for 3.3 V) , 4B: Bank 4B (only for 3.3 V)
VCCIO*xx_yy_zz*	Power	–	Power for I/O banks that are shorted together. *xx*, *yy*, and *zz* are the bank locations. For example: VCCIO1B_1C shorts banks 1B and 1C VCCIO3C_TR_BR shorts banks 3C, TR, and BR
GND	Ground	–	Ground.
CLK*n*	Alternate	Input	Global clock network input. *n* is the number. The number of inputs is package dependent.
CTRL*n*	Alternate	Input	Global network input used for high fanout and global reset. *n* is the number. The number of inputs is package dependent.
PLLIN	Alternate	Input	PLL reference clock resource. There are 5 PLL reference clock resource assignments. Assign the reference clock resource based on the PLL you are using.
MREFCLK	Alternate	Input	MIPI PLL reference clock source.
GPIO*x_n*	GPIO	I/O	General-purpose I/O for user function. User I/O pins are single-ended. *x*: Indicates the bank (L or R) *n*: Indicates the GPIO number.
GPIO*x_n_yyy* GPIO*x_n_yyy_zzz* GPIO*x_zzzn*	GPIO Multi-Function	I/O	Multi-function, general-purpose I/O. These pins are single ended. If these pins are not used for their alternate function, you can use them as user I/O pins. *x*: Indicates the bank; left (L), right (R), or bottom (B). *n*: Indicates the GPIO number. *yyy, yyy_zzz*: Indicates the alternate function. *zzzn*: Indicates LVDS TX or RX and number.
TXN*n*, TXP*n*	LVDS	I/O	LVDS transmitter (TX). *n*: Indicates the number.
RXN*n*, RXP*n*	LVDS	I/O	LVDS receiver (RX). *n*: Indicates the number.
CLKN*n*, CLKP*n*	LVDS	I/O	Dedicated LVDS receiver clock input. *n*: Indicates the number.
RXN*n*_EXTFB*n* RXP*n*_EXTFB*n*	LVDS	I/O	LVDS PLL external feedback. *n*: Indicates the number.
REF_RES	–	–	LVDS reference resistor pin. Connect a 12 kΩ resistor with a tolerance of ±1% to the REF_RES pin with respect to ground.

Table 66: Dedicated Configuration Pins

These pins cannot be used as general-purpose I/O after configuration.

Pins	Direction	Description	Use External Weak Pull-Up
CDONE	Output	Configuration done status pin. CDONE is an open drain output; connect it to an external pull-up resistor to VCCIO. When CDONE = 1, configuration is complete. If you hold CDONE low, the device will not enter user mode.	✓
CRESET_N	Input	Initiates FPGA re-configuration (active low). Pulse CRESET_N low for a duration of t_{creset_N} before asserting CRESET_N from low to high to initiate FPGA re-configuration. This pin does not perform a system reset.	✓
TCK	Input	JTAG test clock input (TCK). The rising edge loads signals applied at the TAP input pins (TMS and TDI). The falling edge clocks out signals through the TAP TDO pin.	✓
TMS	Input	JTAG test mode select input (TMS). The I/O sequence on this input controls the test logic operation . The signal value typically changes on the falling edge of TCK. TMS is typically a weak pull-up; when it is not driven by an external source, the test logic perceives a logic 1.	✓
TDI	Input	JTAG test data input (TDI). Data applied at this serial input is fed into the instruction register or into a test data register depending on the sequence previously applied at TMS. Typically, the signal applied at TDI changes state following the falling edge of TCK while the registers shift in the value received on the rising edge. Like TMS, TDI is typically a weak pull-up; when it is not driven from an external source, the test logic perceives a logic 1.	✓
TDO	Output	JTAG test data output (TDO). This serial output from the test logic is fed from the instruction register or from a test data register depending on the sequence previously applied at TMS. During shifting, data applied at TDI appears at TDO after a number of cycles of TCK determined by the length of the register included in the serial path. The signal driven through TDO changes state following the falling edge of TCK. When data is not being shifted through the device, TDO is set to an inactive drive state (e.g., high-impedance).	✓

ⓘ **Note:** All dedicated configuration pins have Schmitt Trigger buffer. See Table 41: Single-Ended I/O and Dedicated Configuration Pins Schmitt Trigger Buffer Characteristic on page 38 for the Schmitt Trigger buffer specifications.

Table 67: Dual-Purpose Configuration Pins

In user mode (after configuration), you can use these dual-purpose pins as general I/O.

Pins	Direction	Description	Use External Weak Pull-Up
CBUS[2:0]	Input	Configuration bus width select. Connect to weak pull-up resistors if using default mode (x1).	✓
CBSEL[1:0]	Input	Optional multi-image selection input (if external multi-image configuration mode is enabled).	N/A
CCK	I/O	Passive SPI input configuration clock or active SPI output configuration clock (active low). Includes an internal weak pull-up.	N/A
CDI*n*	I/O	*n* is a number from 0 to 31 depending on the SPI configuration. 0: Passive serial data input or active serial output. 1: Passive serial data output or active serial input. *n*: Parallel I/O. In multi-bit daisy chain connection, the CDI*n* (31:0) connects to the data bus in parallel.	N/A
CSI	Input	Chip select. 0: The FPGA is not selected or enabled and will not be configured. 1: Selects the FPGA for configuration.	✓
CSO	Output	Chip select output. Selects the next device for cascading configuration.	N/A
NSTATUS	Output	Status (active low). Indicates a configuration error. When the FPGA drives this pin low, it indicates an ID mismatch, the bitstream CRC check has failed, or remote update has failed.	N/A
SS_N	Input	SPI slave select (active low). Includes an internal weak pull-up resistor to VCCIO during configuration. During configuration, the logic level samples on this pin determine the configuration mode. This pin is an input when sampled at the start of configuration (SS is low); an output in active SPI flash configuration mode. The FPGA senses the value of SS_N when it comes out of reset (pulse CRESET_N low to high). 0: Passive mode 1: Active mode	✓
TEST_N	Input	Active-low test mode enable signal. Set to 1 to disable test mode. During configuration, rely on the external weak pull-up or drive this pin high.	✓
RESERVED_OUT	Output	Reserved pin during user configuration. This pin drives high during user configuration. BGA49 and BGA81 packages only.	N/A

Table 68: MIPI Pinouts (Dedicated)

n Indicates the number. *L* indicates the lane

Function	Group	Direction	Description
VCC25A_MIPI0 VCC25A_MIPI1	Power	–	MIPI 2.5 V analog power supply.
VCC12A_MIPI0_TX VCC12A_MIPI1_TX	Power	–	MIPI 1.2 V TX analog power supply.
VCC12A_MIPI0_RX VCC12A_MIPI1_RX	Power	–	MIPI 1.2 V RX analog power supply.
GNDA_MIPI	Ground	–	Ground for MIPI analog power supply.
MIPI*n*_TXDP*L* MIPI*n*_TXDN*L*	MIPI	I/O	MIPI differential transmit data lane.
MIPI*n*_RXDP*L* MIPI*n*_RXDN*L*	MIPI	I/O	MIPI differential receive data lane.
MREFCLK	Clock	Input	MIPI PLL reference clock source.

Efinity Software Support

The Efinity® software provides a complete tool flow from RTL design to bitstream generation, including synthesis, place-and-route, and timing analysis. The software has a graphical user interface (GUI) that provides a visual way to set up projects, run the tool flow, and view results. The software also has a command-line flow and Tcl command console. The Efinity® software supports simulation flows using the ModelSim, NCSim, or free iVerilog simulators. An integrated hardware Debugger with Logic Analyzer and Virtual I/O debug cores helps you probe signals in your design. The software-generated bitstream file configures the T13 FPGA. The software supports the Verilog HDL and VHDL languages.

T13 Interface Floorplan

> **Note:** The numbers in the floorplan figures indicate the GPIO and LVDS number ranges. Some packages may not have all GPIO or LVDS pins in the range bonded out. Refer to the **T13 pinout** for information on which pins are available in each package.

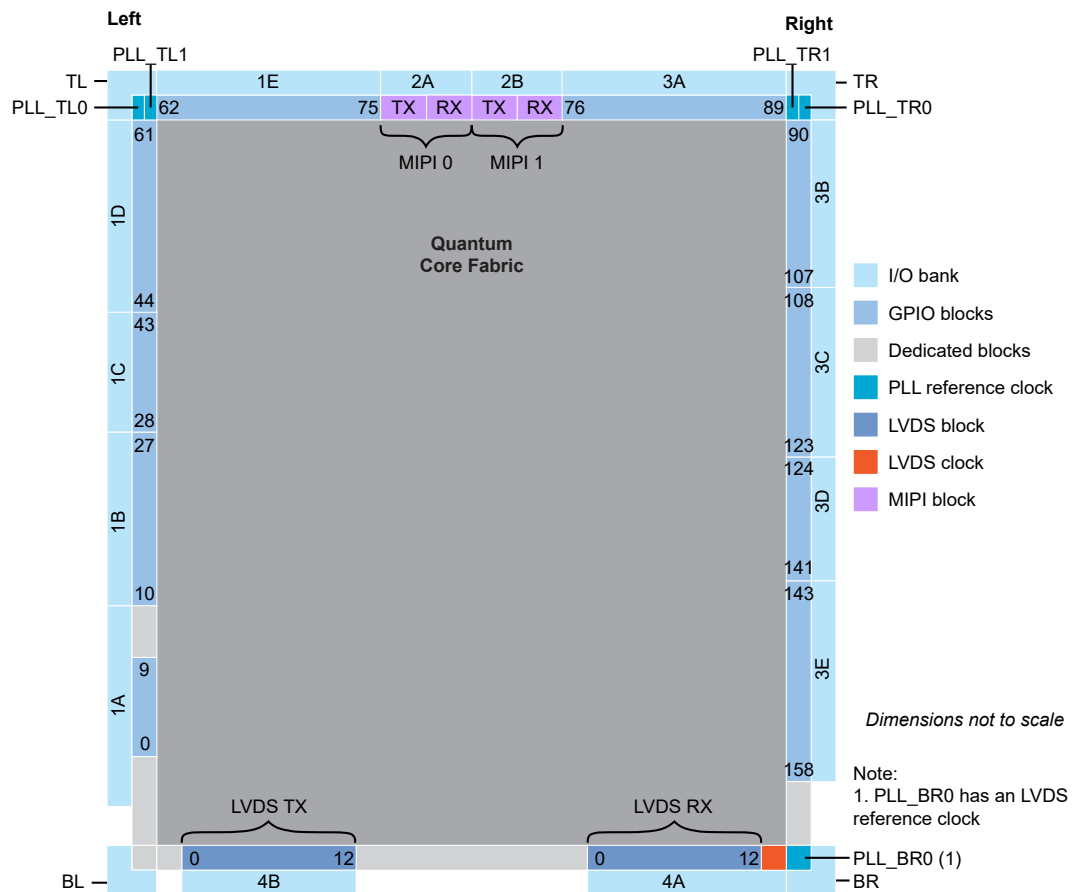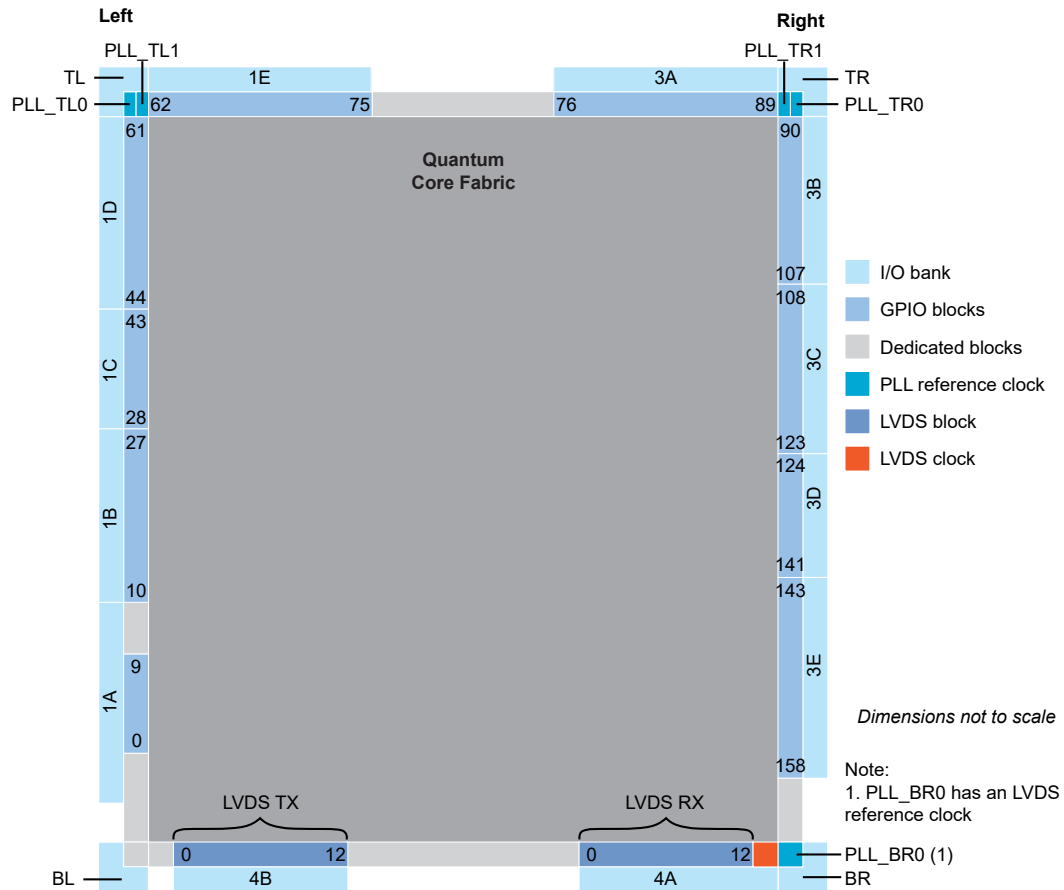*Figure 32: Floorplan Diagram for BGA169 Packages (with MIPI)*

Figure 33: Floorplan Diagram for BGA256 Packages

Ordering Codes

Refer to the **Trion Selector Guide** for the full listing of T13 ordering codes.

Revision History

Table 69: Revision History

Date	Version	Description
August 2021	2.13	Added internal weak pull-up and pull-down resistor specs. (DOC-485)
		Updated table title for Single-Ended I/O Schmitt Trigger Buffer Characteristic. (DOC-507)
		Added note in Pinout Description stating all dedicated configuration pins have Schmitt Trigger buffer. (DOC-507)
June 2021	2.12	Updated CRESET_N pin description. (DOC-450)
April 2021	2.11	Updated PLL specs; t_{ILJIT} (PK - PK) and t_{DT}. (DOC-403)
		Added note about limiting number of LVDS as GPIO output and bidirectional per I/O bank to avoid switching noise. (DOC-411)
March 2021	2.10	Added LVDS TX reference clock output duty cycle and lane-to-lane skew specs. (DOC-416)
March 2021	2.9	Added automotive speed grade (Q4) specs for BGA169 package. (DOC-399)
February 2021	2.8	Added I/O input voltage, V_{IN} specification. (DOC-389)
		Added LVDS TX data and timing relationship waveform. (DOC-359)
		Added LVDS RX I/O electrical specification waveform. (DOC-346)
December 2020	2.7	Updated NSTATUS pin description. (DOC-335)
		Added data for C4L and I4L DC speed grades. (DOC-268)
		Updated PLL reference clock input note by asking reader to refer to PLL Timing and AC Characteristics. (DOC-336)
		Added other PLL input clock frequency sources in PLL Timing and AC Characteristics. (DOC-336)
		Removed OE and RST from LVDS block as they are not supported in software. (DOC-328)
		Added a table to Power Up Sequence topic describing pin connection when PLL, GPIO, or MIPI is not used. (DOC-325)
		Updated f_{MAX_S} for passive configuration modes. (DOC-350)
		Updated f_{MAX_S} for passive configuration modes. (DOC-350)
September 2020	2.6	Updated pinout links.
		Corrected speed grades for single-ended I/O and LVDS configured as single-ended I/O f_{MAX}.

Date	Version	Description
August 2020	2.5	Update MIPI TX and RX Interface Block Diagram to include signal names.
		Updated REF_CLK description for clarity.
		Added recommended operating conditions and f_{MAX} for C4L and I4L speed grades.
		Updated t_{USER} timing parameter values and added a note about the conditions for the values.
		Updated description for GPIO pins state during configuration to exclude LVDS as GPIO.
		Added f_{MAX} for single-ended I/O and LVDS configured as single-ended I/O.
		Added maximum power supply current transient during power-up.
July 2020	2.4	Removed preliminary note from MIPI electrical specifications and timing. These specifications are final.
		Updated timing parameter symbols in boundary scan timing waveform to reflect JTAG mode parameter symbols.
		Added supported GPIO features.
		Updated the maximum F_{VCO} for PLL to 1,600 MHz.
		Updated the C divider requirement for the 90 degrees phase shift in the PLL Interface Designer Settings - Manual Configuration Tab.
		Updated LVDS electrical specifications note about RX differential I/O standard support, and duplicated the note in LVDS functional description topic.
		Added note to LVDS RX interface block diagram.
		Added note to recommended power-up sequence about MIPI power guideline.
		Updated I/O bank names from TL_CORNER, BL_CORNER, TR_CORNER, and BR_CORNER to TL, BL, TR, and BR respectively.
		Updated the term DSP to multiplier.
		Updated power up sequence description about holding CRESET_N low.
		Updated PLLCLK pin name to PLL_CLKIN.
		Added PLL_EXTFB and MIPI_CLKIN as an alternative input in GPIO signals table for complex I/O buffer.
		Updated PLL names in PLL reference clock resource assignments.
		Updated supported configuration modes.
		Updated typical leakage current to 6.8 mA and add a note stating it is applicable to BGA256 package.
February 2020	2.3	Added f_{MAX} for DSP blocks and RAM blocks. In MIPI RX and TX interface description, updated maximum data pixels for RAW10 data type.
		Added MIPI reset timing information.
		Added Trion power-up sequence. MIPI power-up moved to this topic.
		VCC12A_MIPI_TX, VCC12A_MIPI_RX maximum recommended operating condition changed to 1.25 V.
		Added number of global clocks and controls that can come from GPIO pins to package resources table.

Date	Version	Description
December 2019	2.2	Updated PLL Interface Designer settings. Removed MIPI data type bit settings. Refer to AN 015: Designing with the Trion MIPI Interface for the bit settings. Removed DIV1 and DIV2 active mode configuration frequencies; they are not supported. Added note to LVDS electrical specifications about RX differential I/O standard support.
October 2019	2.1	Added explanation that 2 unassigned pairs of LVDS pins should be located between and GPIO and LVDS pins in the same bank. Updated the reference clock pin assignments for TL_PLL0 and TL_PLL1. Added waveforms for configuration timing.
August 2019	2.0	Updated MIPI interface description. Under Ordering Codes, linked to Trion FPGA Selector Guide.
May 2019	1.0	Updated MIPI description, DC characteristics, and pin information. Updated timing specifications. Added information on the signal interface.
January 2019	0.5	Added information on DDIO support.
December 2018	0.4	Updated the package options.
November 2018	0.3	Added GNDA_xx (PLL analog ground) to pinout. Change VSSxxA_MIPI pinout to GNDxxA_MIPI. Updated PLL block diagram and clarified feedback paths. Added floorplan information. Updated pinout table. Updated packaging options.
October 2018	0.2	Updated LVDS serialization factors.
October 2018	0.1	Initial release.